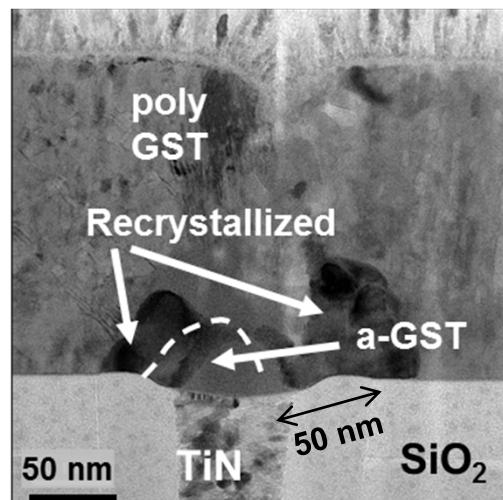


15th International Workshop on Computational Electronics
Phonon School May 21, 2012

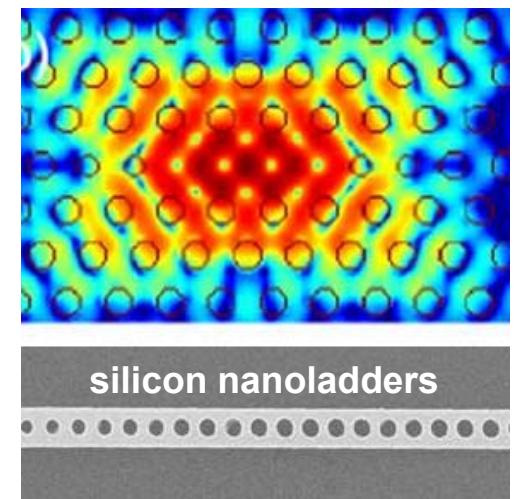
Phonons in NanoElectronics



With Wong Group,
Stanford EE

Ken Goodson
Mechanical Engineering
Stanford University

STANFORD
nanohot



With Vuckovic Group,
Stanford EE

Electronics Thermal Challenges

servers



energy efficiency

portables



hotspot mitigation

*heterogeneous
integration*



transportation



defense

Electronics Thermal Challenges

servers



BAE SYSTEMS

portables



BOSCH



GROUP4 LABS™
AN EXTREME MATERIALS COMPANY

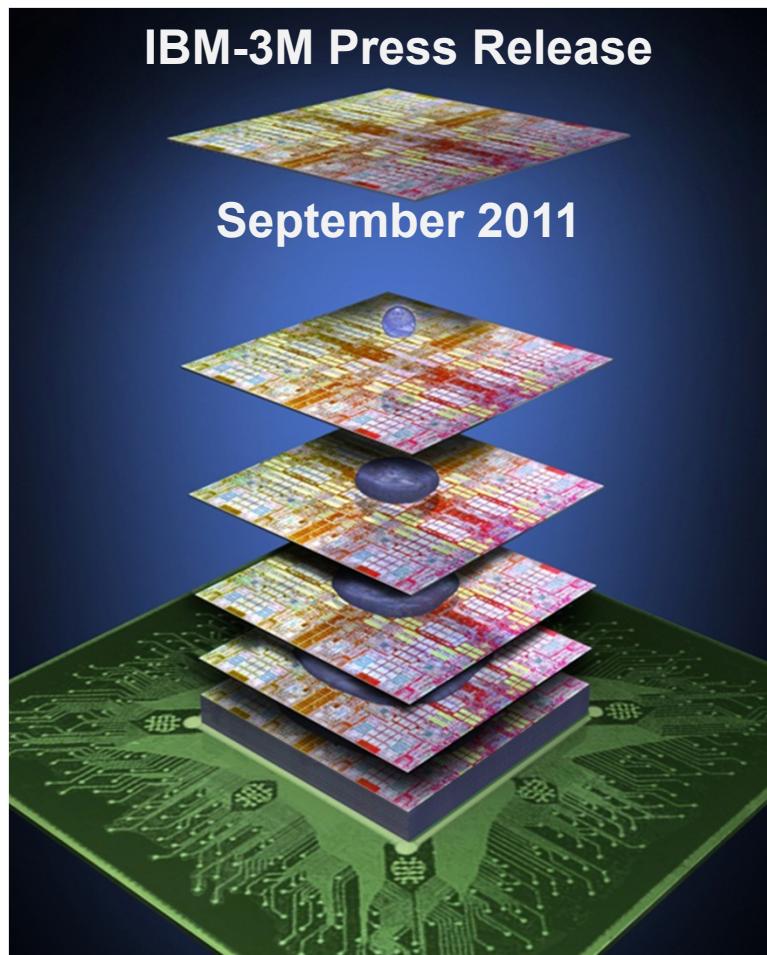


transportation



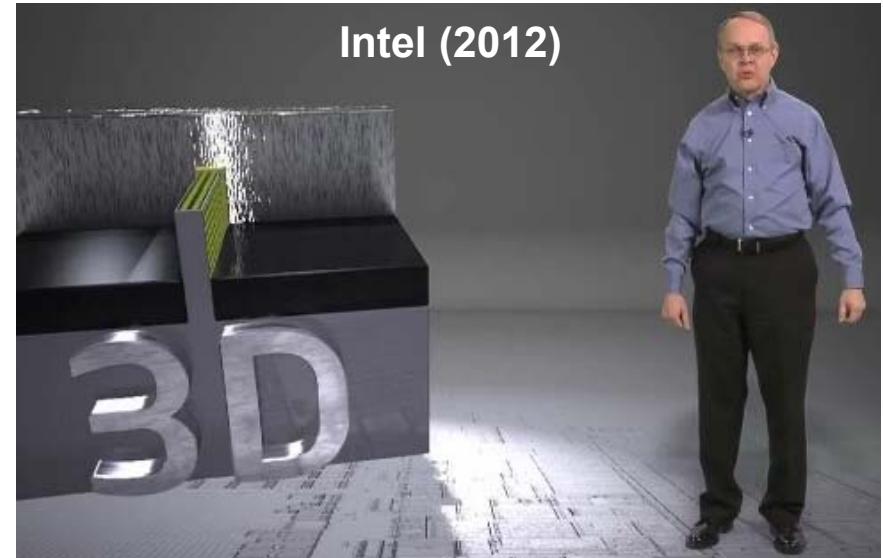
defense

Electronics Cooling in the News



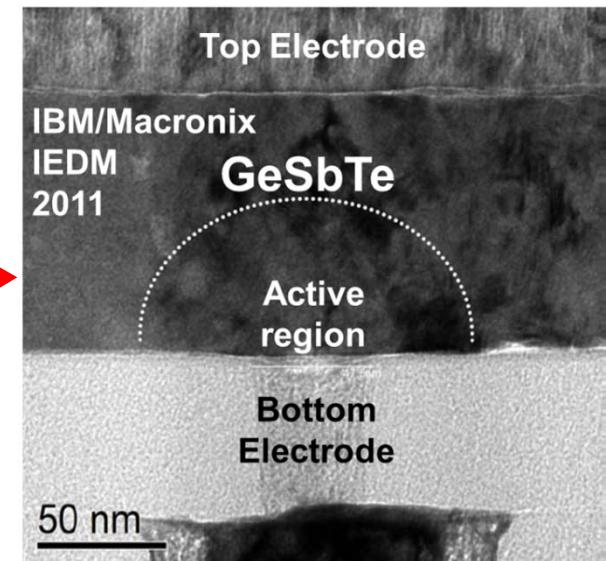
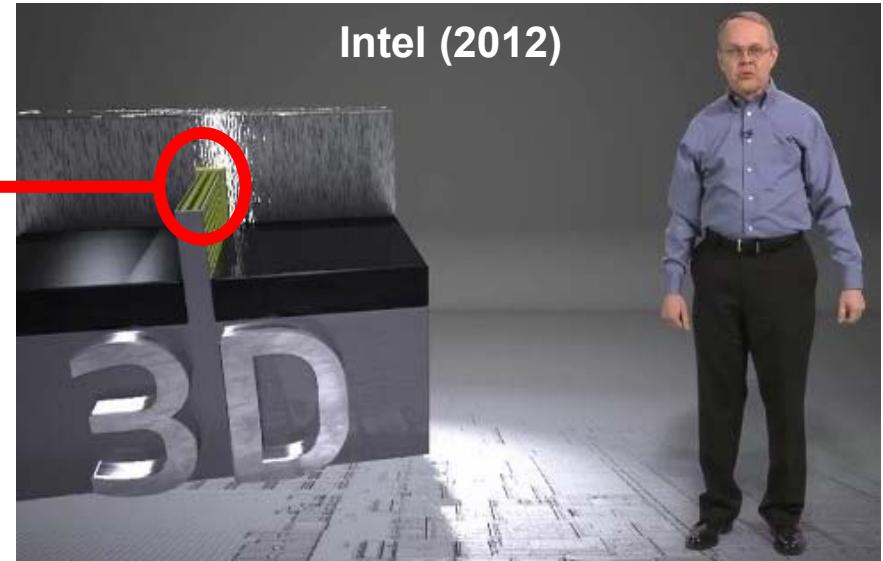
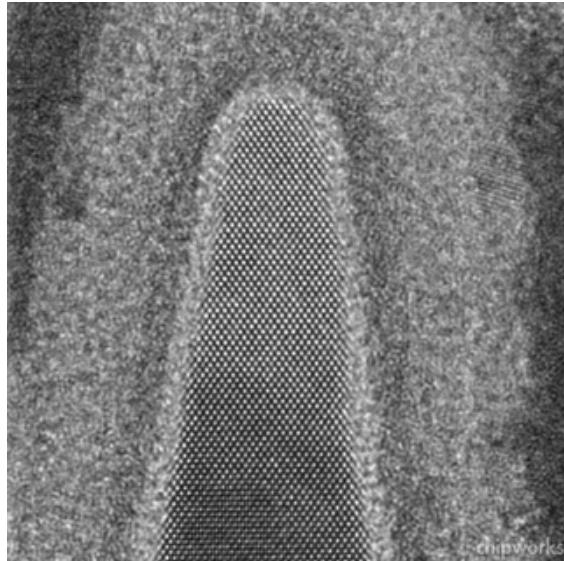
Phonons in the News?

Finally, commercial finFETs

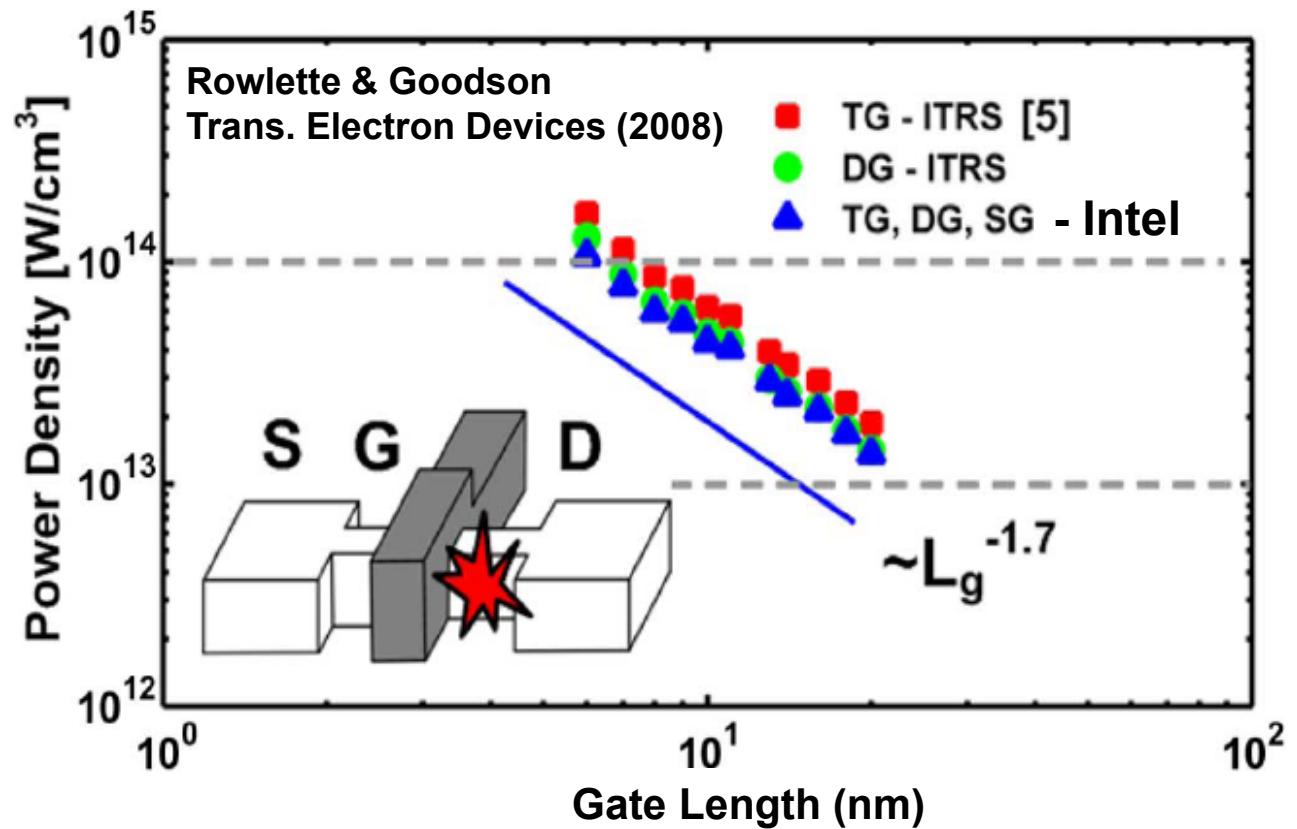
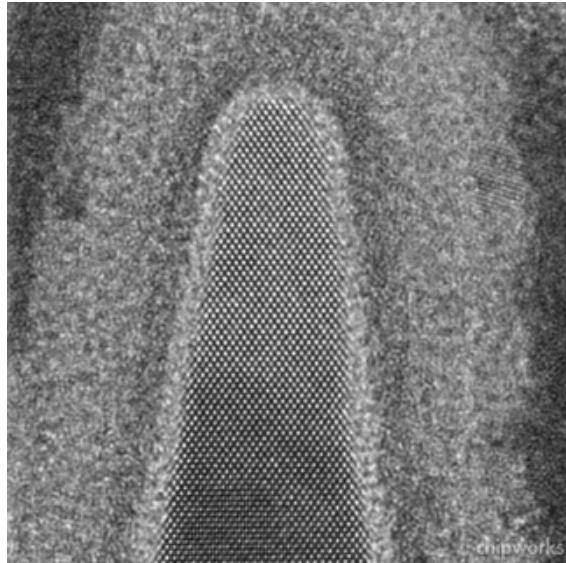


Finally, commercial
phase change memory

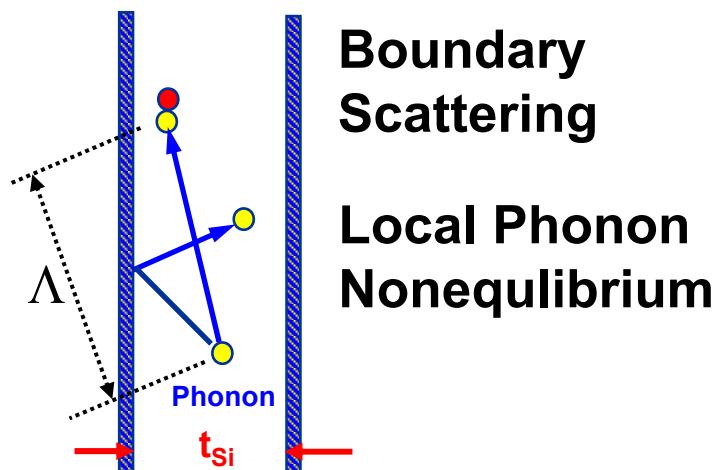
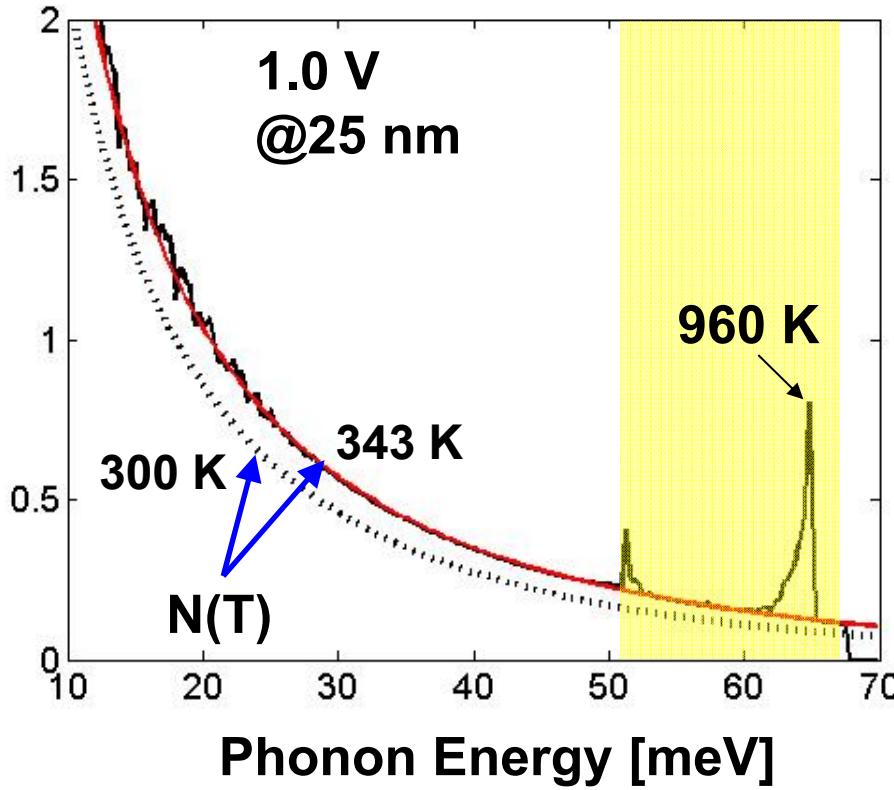
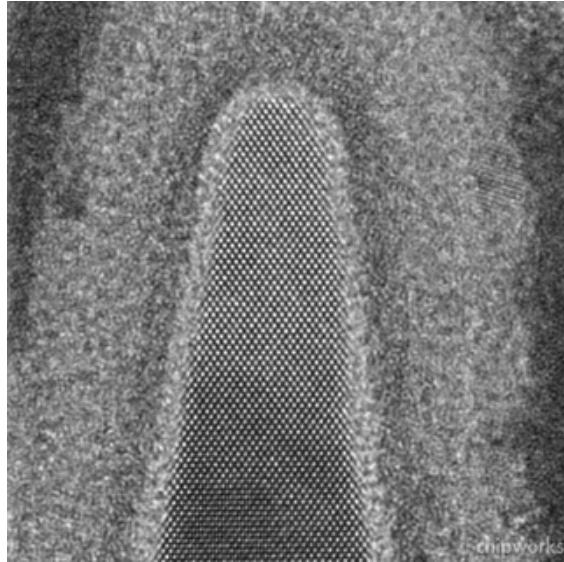
Phonons in the News?



Phonons in the News?



Phonons in the News?

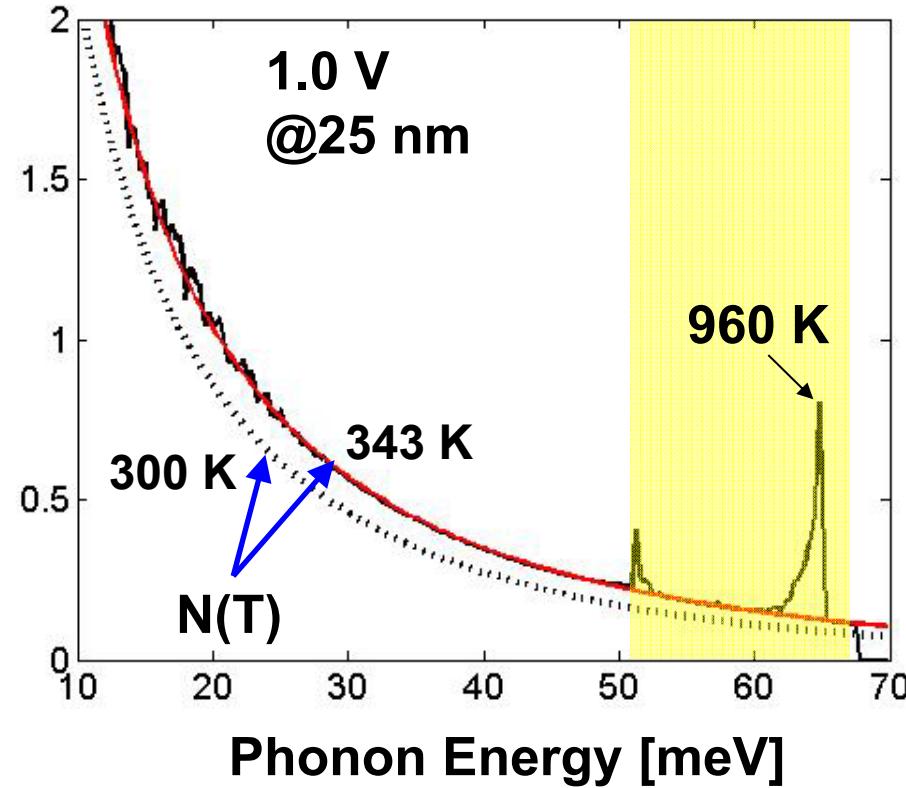
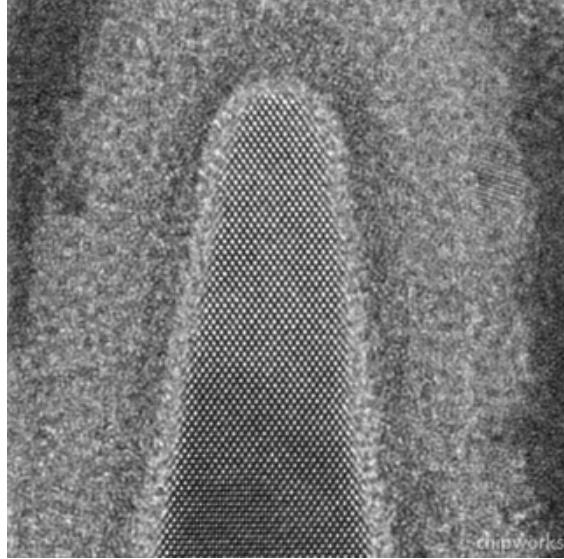


Proceedings^{OF THE}**IEEE**
**Heat Generation and Transport
in Nanometer-Scale Transistors**

By ERIC POP, SANJIV SINHA, AND KENNETH E. GOODSON

VOL. 94 (2006) 

Phonons in the News?



**Branch Nonequilibrium
(BTE Moments)**

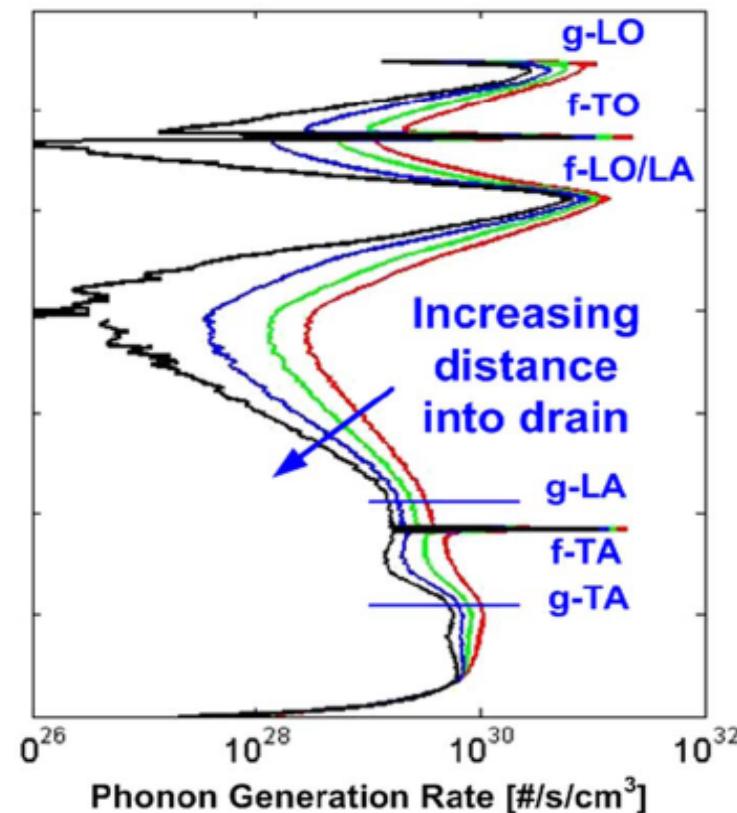
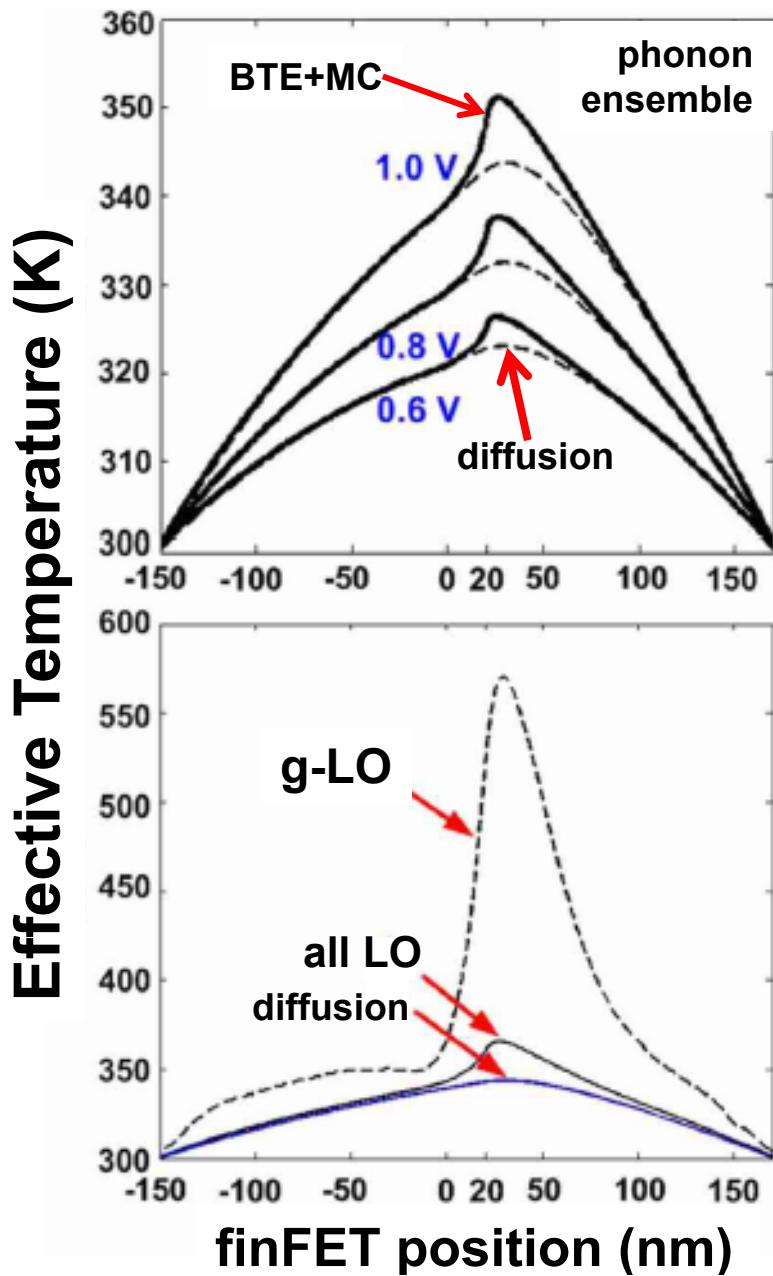
(Lai and Arun Majumdar 1996)

Hotspot Emission (BTE)
(Gang Chen 1996)

**Boundary Scattering
(SOI MOSFET)**

(Goodson & Flik 1992;
Sverdrup et al. 2001)

Phonons in the News?



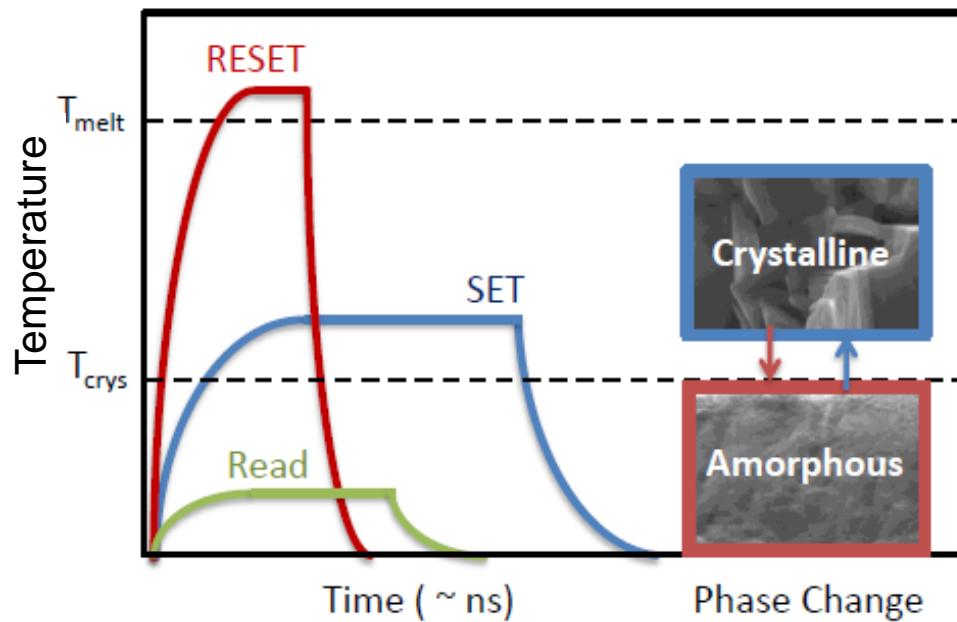
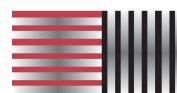
Coupled Electron Monte Carlo &
Phonon BTE in 20 nm finFET
IEEE TRANS. ELECTRON DEVICES (55) 2008
Jeremy A. Rowlette and Kenneth E. Goodson

Phonons in the News?

Proceedings OF THE IEEE Phase Change Memory

WONG, RAOUX, KIM, LIANG, REIFENBERG,
RAJENDRAN, ASHEGHI, AND GOODSON

VOL. 98 (2010)

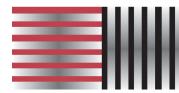


Phonons in the News?

Proceedings OF THE IEEE Phase Change Memory

WONG, RAOUX, KIM, LIANG, REIFENBERG,
RAJENDRAN, ASHEGHI, AND GOODSON

VOL. 98 (2010)



Lee, Asheghi, Goodson,
Nanotechnology (2012)

Phonons in PCRAM

Electrode Interface

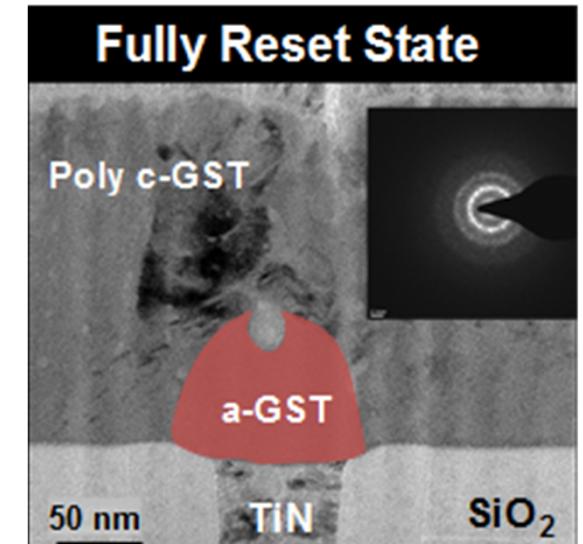
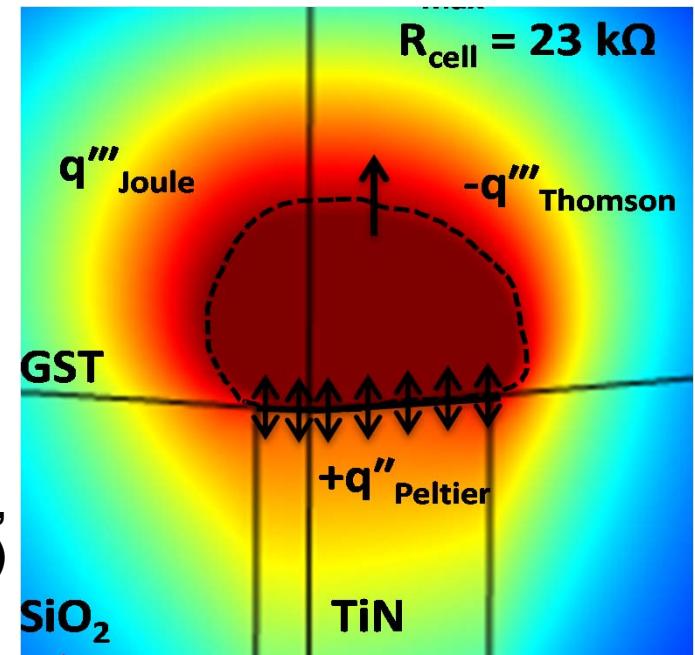
(Reifenberg et al., 2007 & 2008)

Phase Interfaces & Electrons

(Bozorg-Grayeli, 2011)

Thermoelectric Phenomena

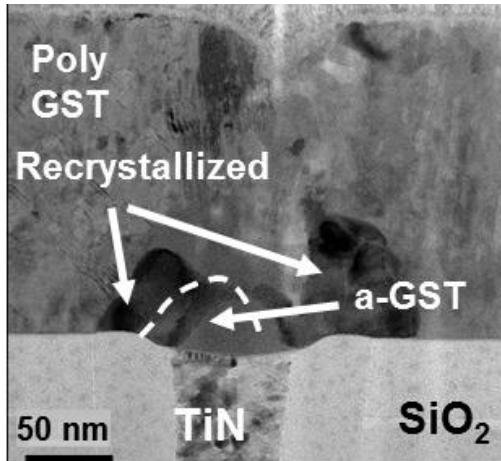
(Lee et al., 2012)



(Kuzum, Wong, et al, 2011/2012)

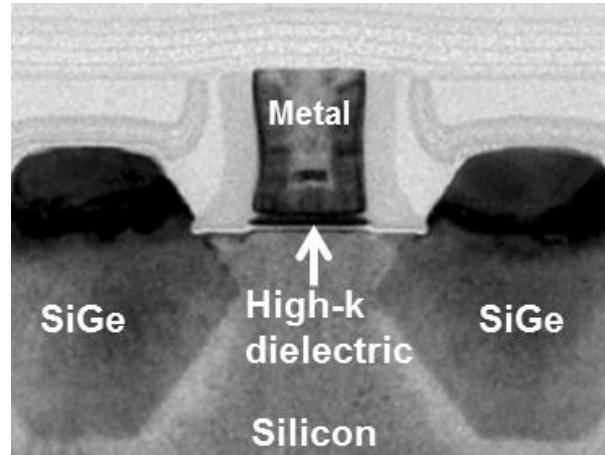
STANFORD nanoHeat

Phase Change NanoCells



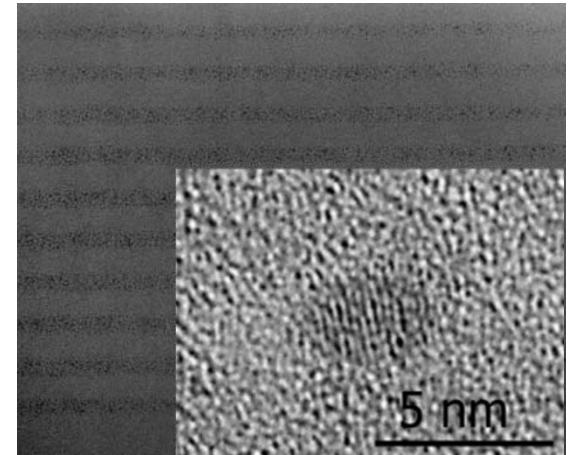
with Intel TMG, IBM (SRC)
and Wong Group, Stanford EE

NanoFETs



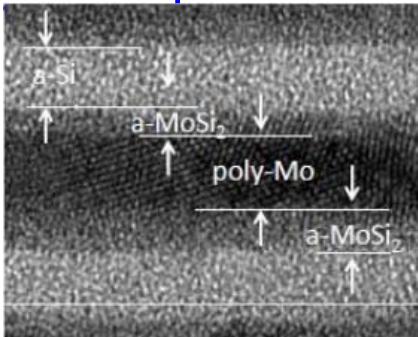
with Intel ATD (SRC)

Optical Nanocrystals



with Brongersma group,
Stanford MSE

Extreme UV Optics



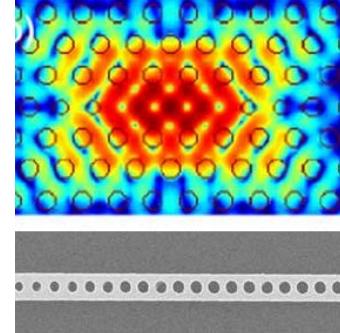
with KLA Tencor

GaN-Diamond Composites



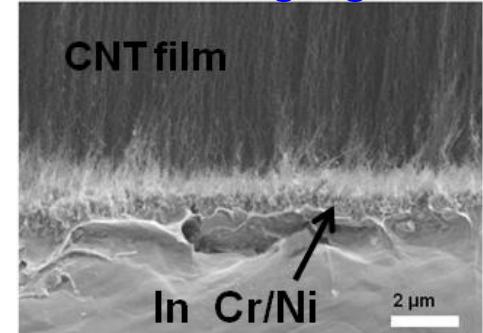
with Raytheon, Boeing,
Boeing, BAE (DARPA NJTT)

Quantum Cavity Lasers



with Vuckovic group,
Stanford EE

Nanostructured Packaging



with Bosch
(NSF/DOE Partnership)



Current Group

Josef Miler
Michael Barako
Jaeho Lee
Sri Lingamneni
Saniya Leblanc
Jungwan Cho

Elah Bozorg-Grayeli
Amy Marconnet
Shilpi Roy (EE)
Yuan Gao
Yiyang Li (MSE)
Zijian Li

Ken Goodson

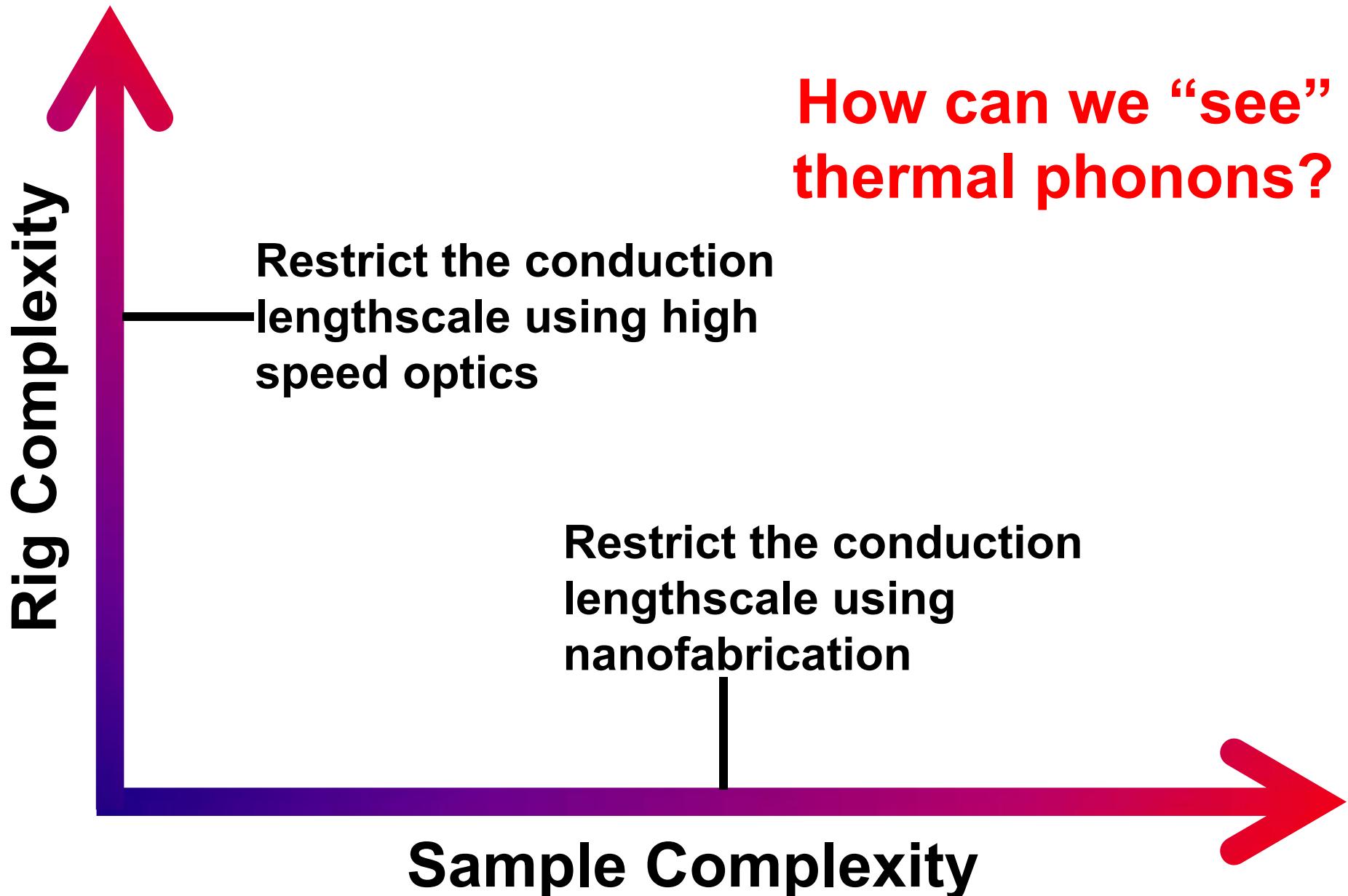
Lewis Hom
Aditja Sood (MSE)
Woosung Parc

Dr. Takashi Kodama
Dr. Yoonjin Won
Prof. Mehdi Asheghi

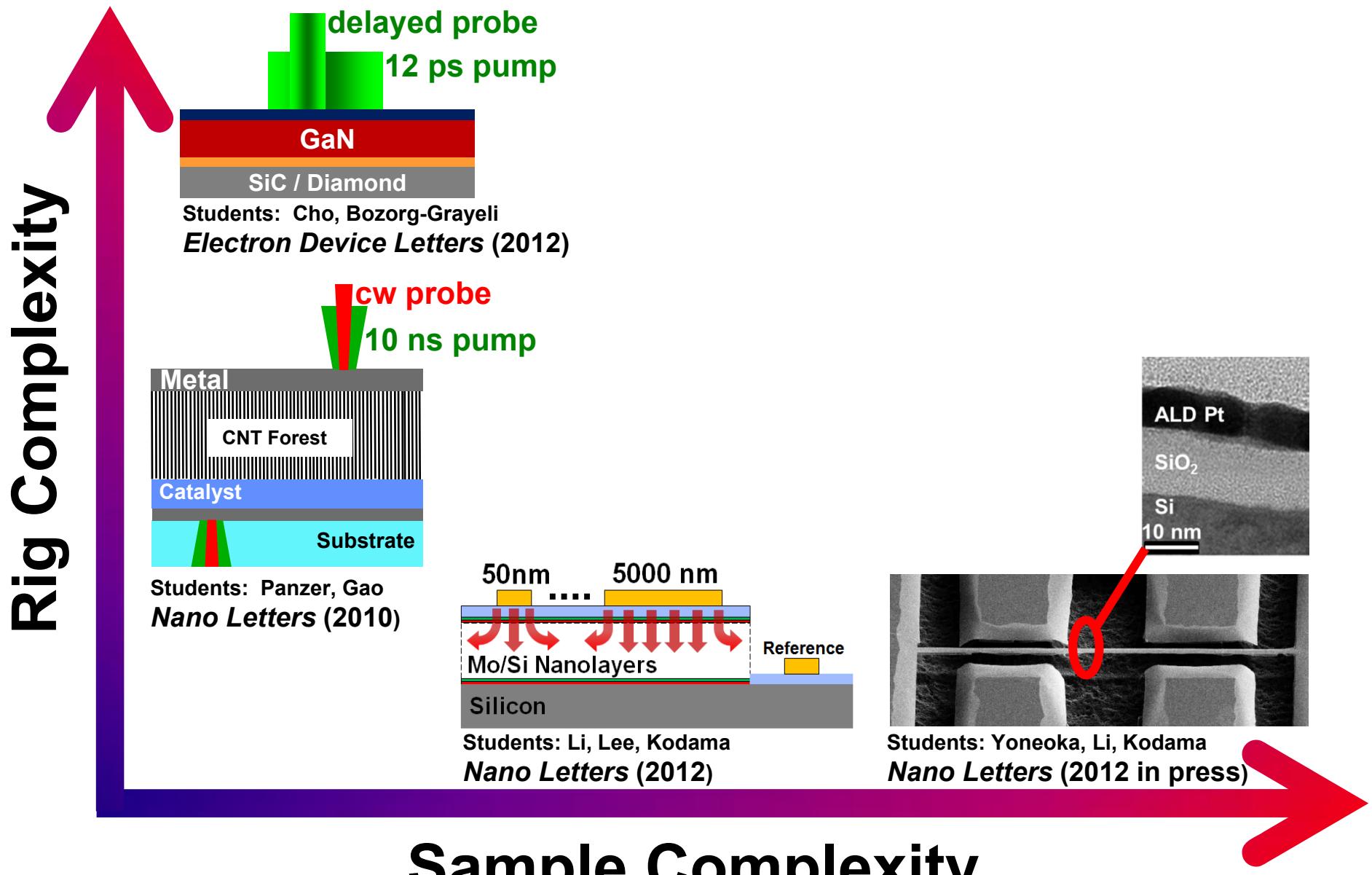
Selected Alumni

Prof. Dan Fletcher	UC Berkeley	Dr. Jeremy Rowlette	Daylight Solns
Prof. Evelyn Wang	MIT	Dr. Patricia Gharagozloo	Sandia Labs
Prof. Katsuo Kurabayashi	U. Michigan	Dr. Per Sverdrup	Intel
Prof. Sungtaek Ju	UCLA	Dr. Chen Fang	Exxon-Mobile
Prof. Mehdi Asheghi	Stanford	Dr. Milnes David	IBM
Prof. Bill King	UIUC	Dr. Max Touzelbaev	AMD
Prof. Eric Pop	UIUC (EE)	Dr. Roger Flynn	Intel
Prof. Sanjiv Sinha	UIUC	Dr. Julie Steinbrenner	Xerox Parc
Prof. Xuejiao Hu	Wuhan Univ.	Dr. John Reifenberg	Intel
Prof. Carlos Hidrovo	UT Austin	Dr. David Fogg	Creare
Prof. Kaustav Banerjee	UCSB (EE)	Dr. Matthew Panzer	KLA-Tencor
Prof. Ankur Jain	UT Arlington		
Prof. Sarah Parikh	Foothill College		

Nano Thermal Metrology



Nano Thermal Metrology



Phonons in Nanowires & NanoTubes

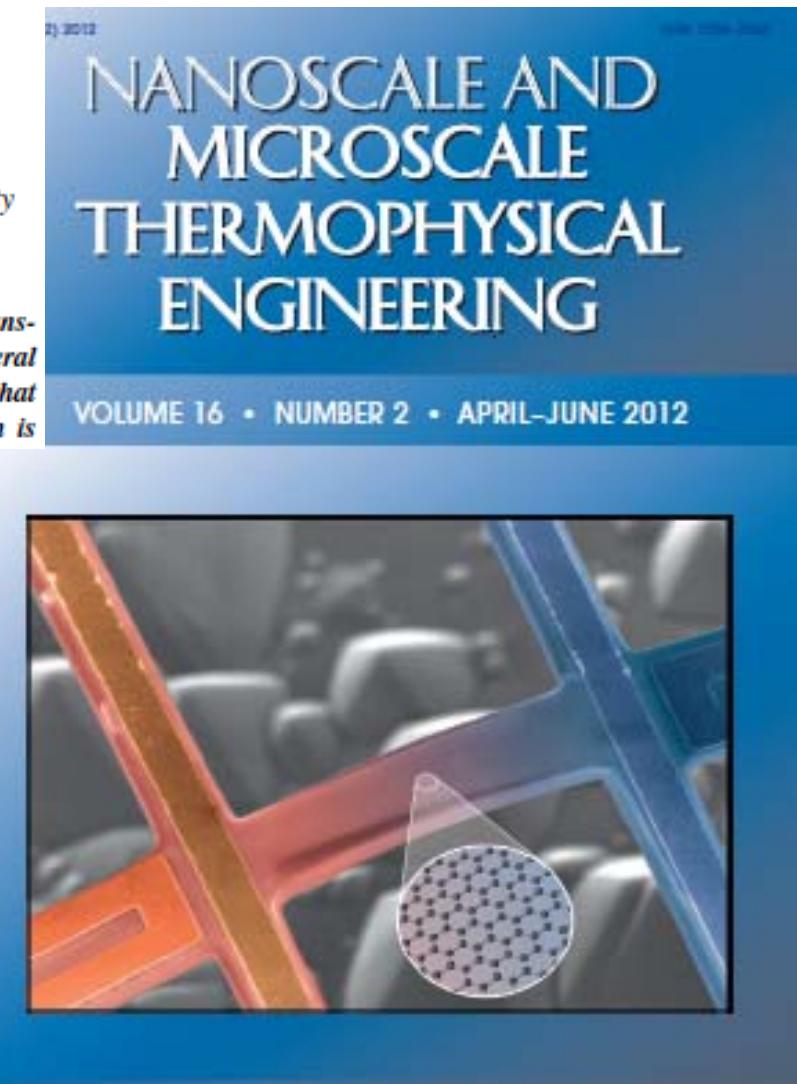
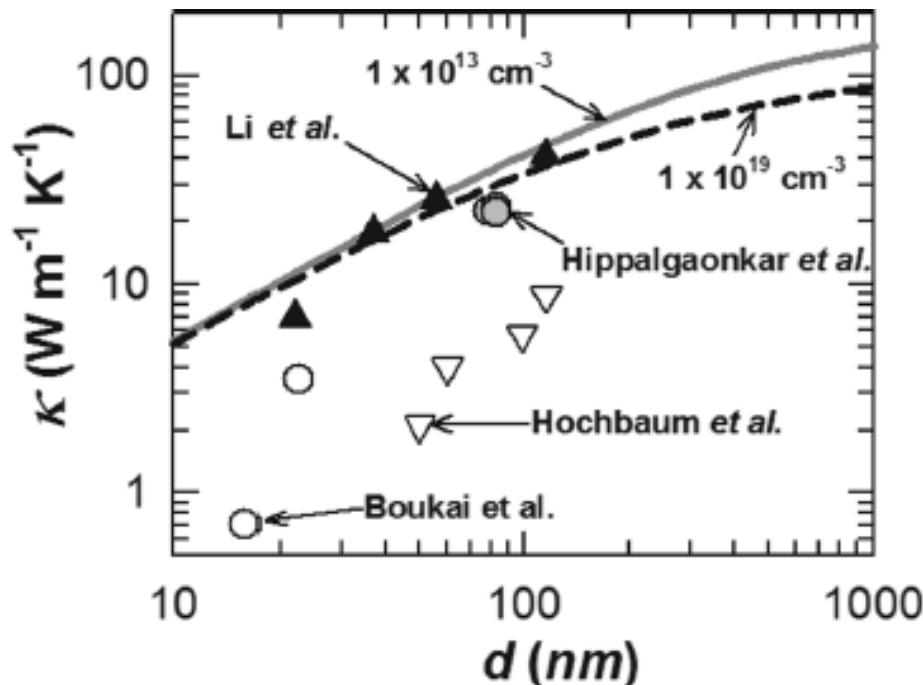
Appearing this month from Li Shi, UT Austin

THERMAL AND THERMOELECTRIC TRANSPORT IN NANOSTRUCTURES AND LOW-DIMENSIONAL SYSTEMS

Li Shi

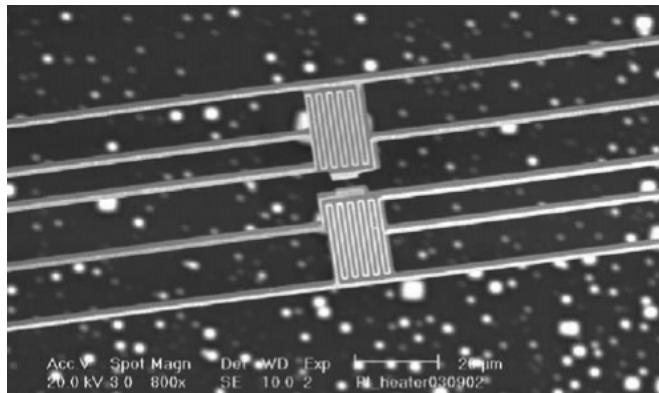
Department of Mechanical Engineering, Texas Materials Institute, The University of Texas at Austin, Austin, Texas

Significant progress has been made in recent studies of thermal and thermoelectric transport phenomena in nanostructures and low-dimensional systems. This article reviews several intriguing quantum and classical size effects on thermal and thermoelectric properties that have been predicted by theoretical calculations or observed in experiments. Attention is

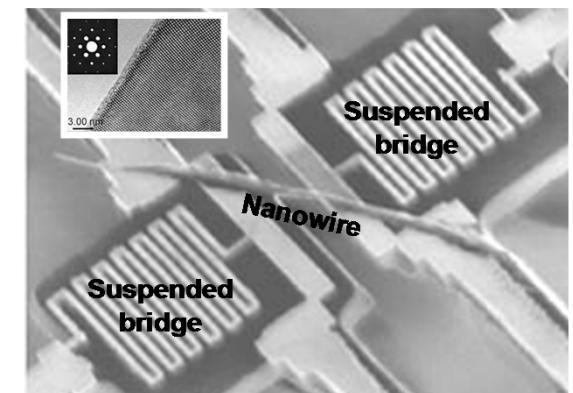


Phonons in Nanowires & NanoTubes

External Heating



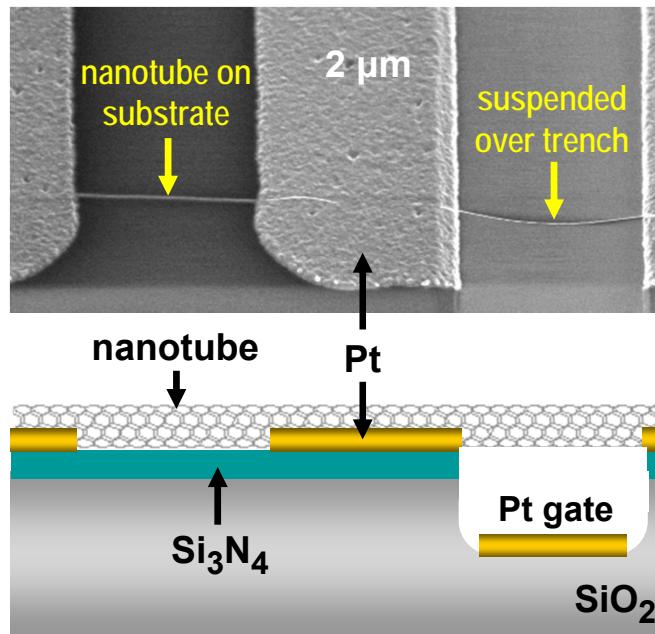
Shi and Li, JHT (2003)
Yu, Shi et al., Nanoletters (2005)



Li, Majumdar, Yang, et al.
Applied Physics Letters (2003)

McConnell, Goodson
et al. (2004)

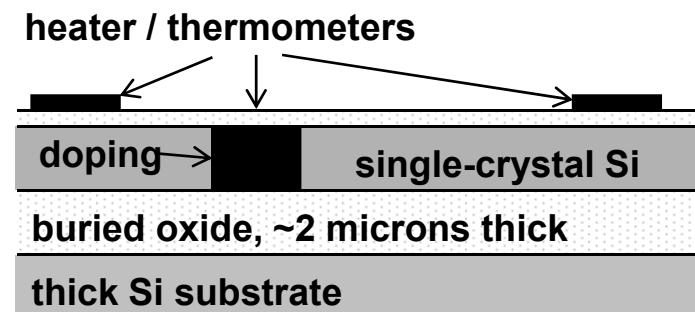
Internal Heating



Pop, Goodson, Dai et al., *Nano Letters* (2006),
Pop, Goodson, Dai et al., *Physical Review Letters* (2005)

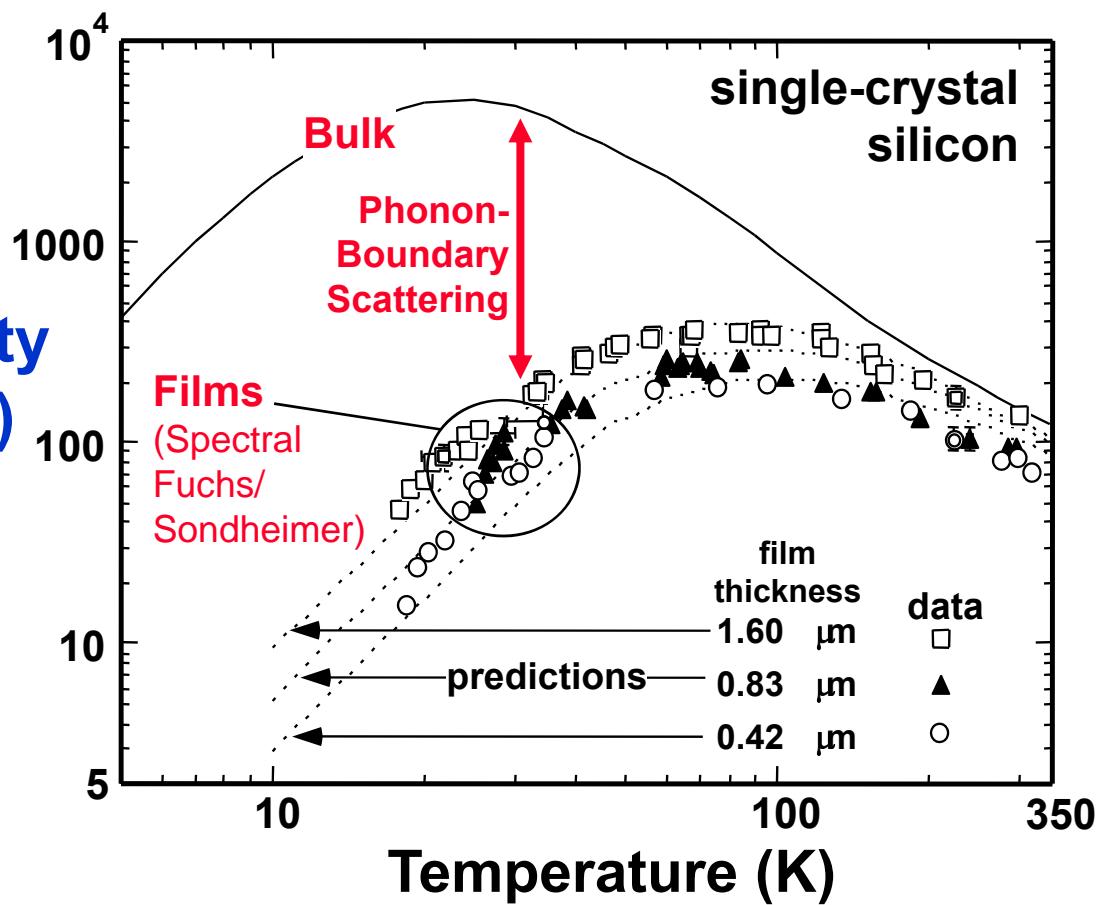
SOI-Enabled Phonon Studies 1994-

Measurement Structure

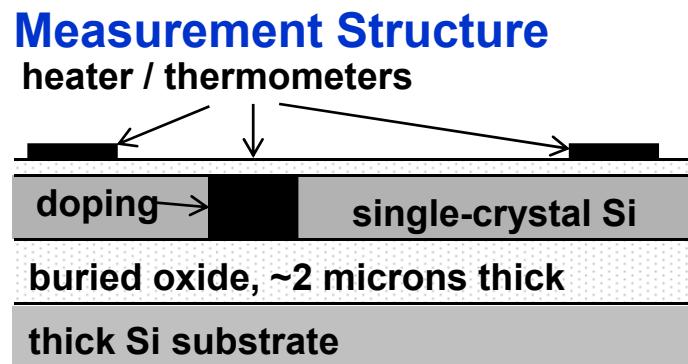


Thermal
Conductivity
($\text{W m}^{-1} \text{K}^{-1}$)

Asheghi, Goodson, et al.,
Applied Physics Letters 71 (1997)
Asheghi, Goodson, et al.,
J. Heat Transfer 120 (1998)



SOI-Enabled Phonon Studies 1994-

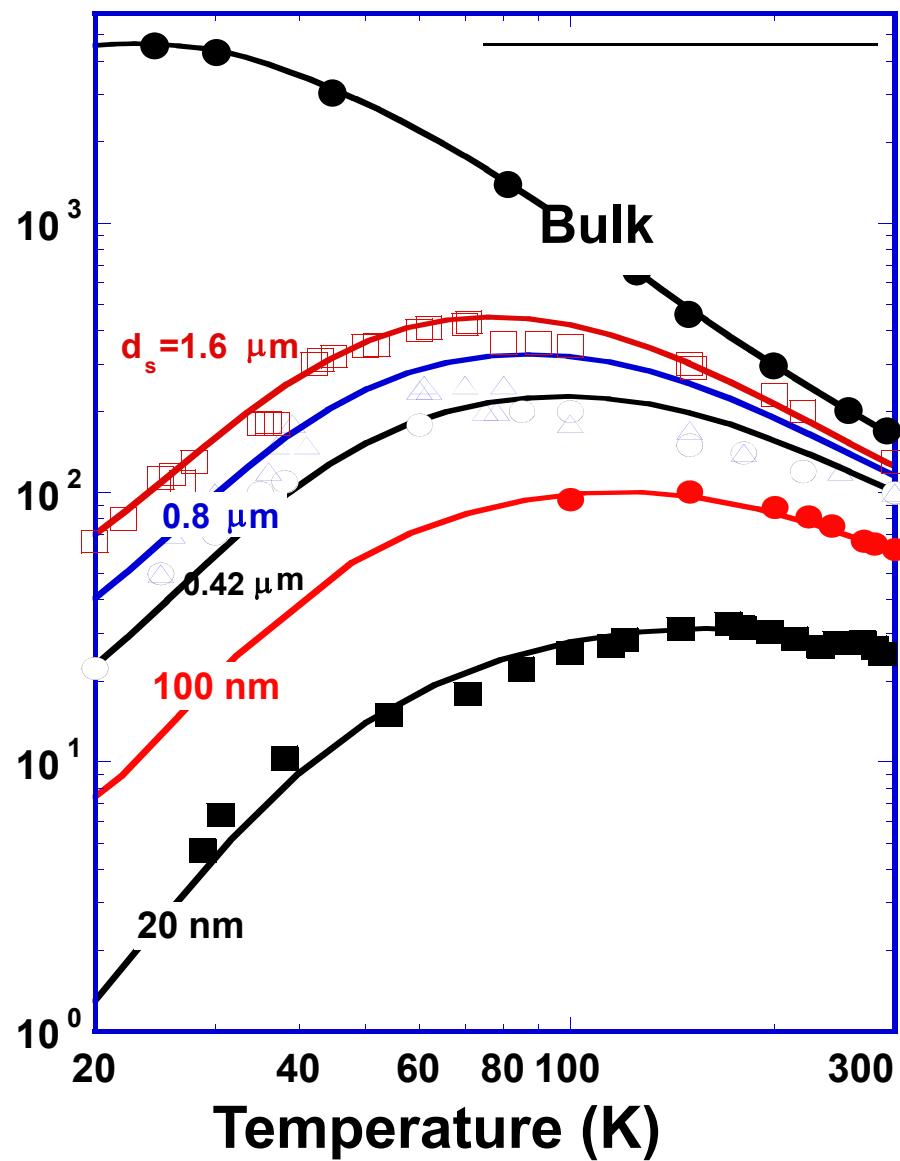


Thermal
Conductivity
($\text{W m}^{-1} \text{K}^{-1}$)

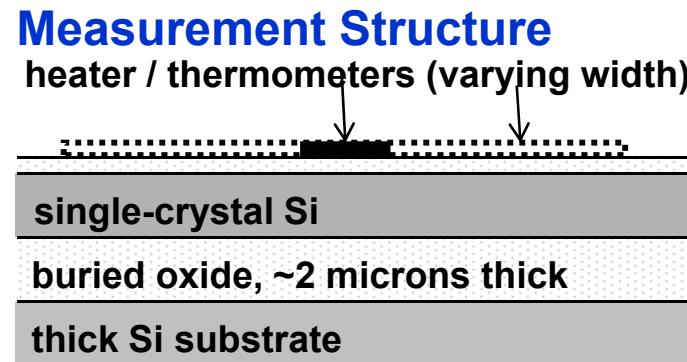
Asheghi, Goodson, et al.,
Applied Physics Letters 71 (1997)

Asheghi, Goodson, et al.,
J. Heat Transfer 120 (1998)

Liu and Asheghi
J. Heat Transfer 120 (2006)



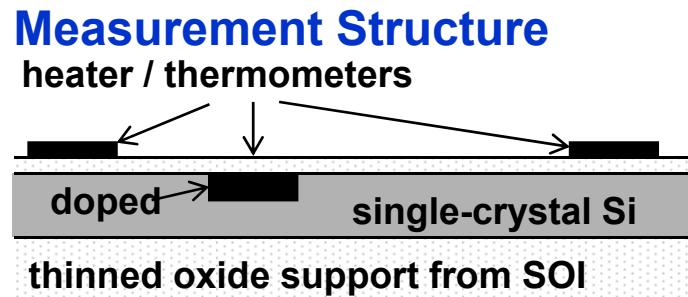
SOI-Enabled Phonon Studies 1994-



Y. Sungtaek Ju
now with UCLA MAE

Ju, Goodson
Applied Physics Letters 74 (1999)

SOI-Enabled Phonon Studies 1994-

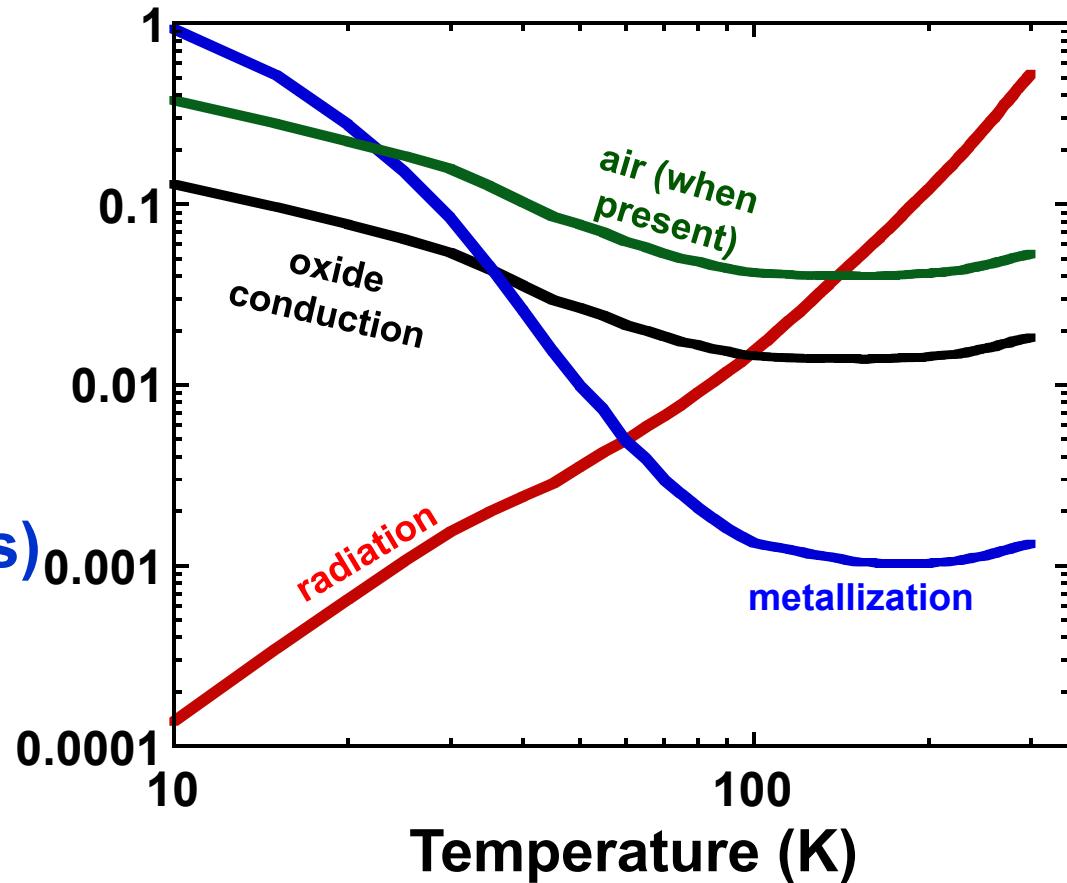


Vacuum
(suspended structure)

**Thermal
Resistance
Ratio
(SILICON / loss)**

Sverdrup, Sinha, Goodson et al.,
Applied Physics Letters 78 (2001)

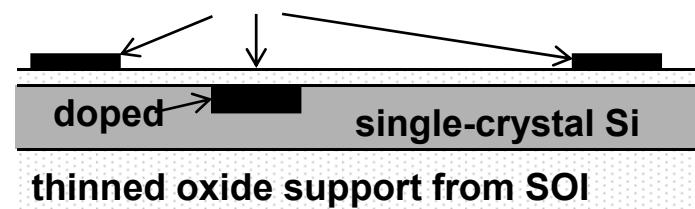
McConnell, Srinivasan, Goodson,
et al., *JMEMS* 10 (2001)



SOI-Enabled Phonon Studies 1994-

Measurement Structure

heater / thermometers

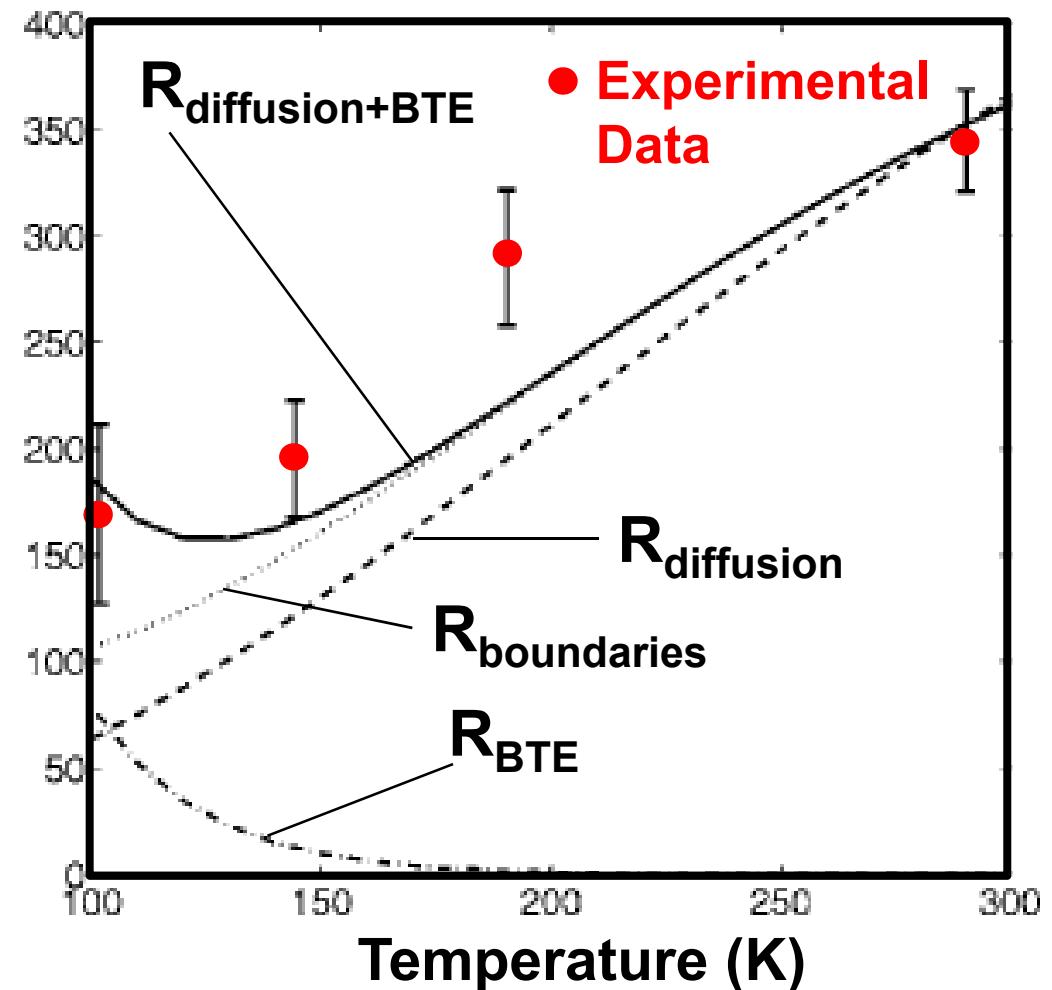


Vacuum
(suspended structure)

Thermal
Resistance
(K W^{-1})

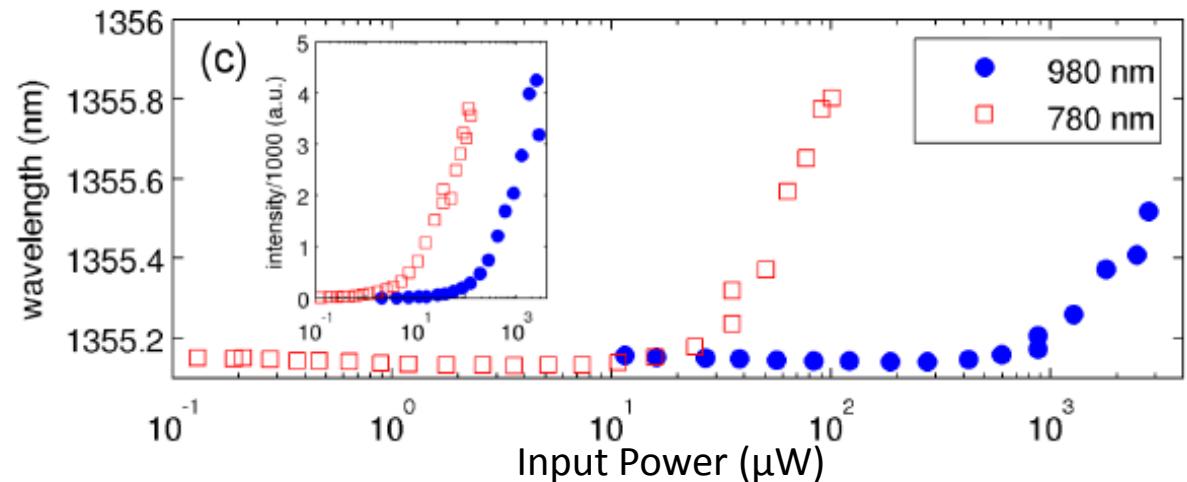
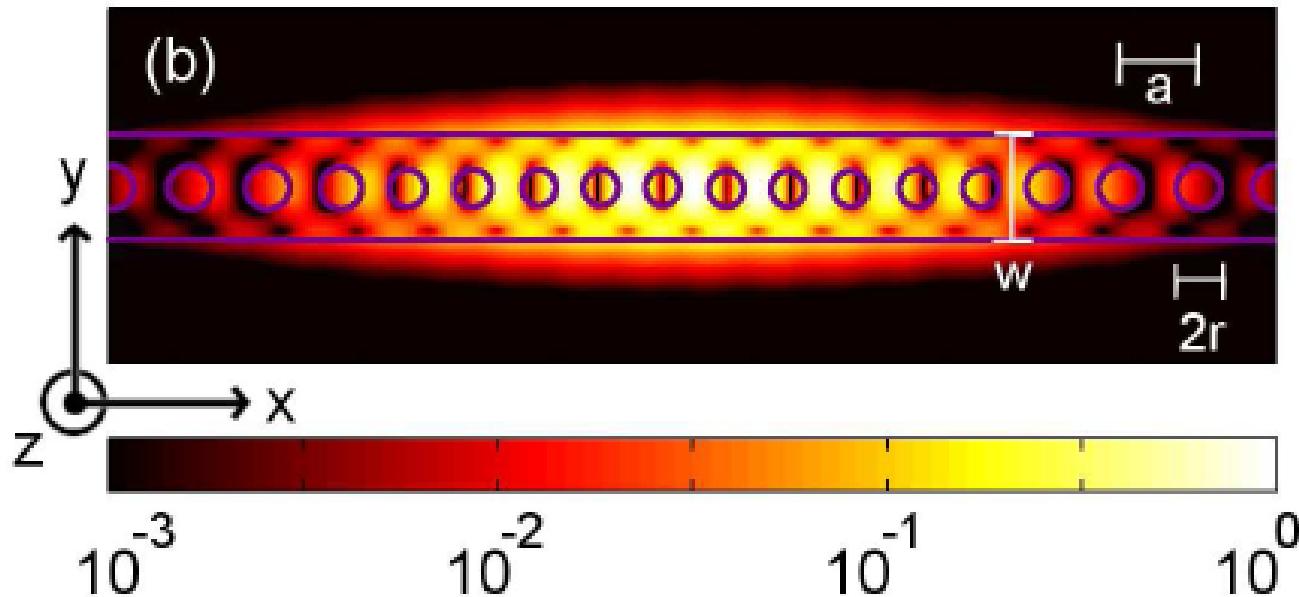
Sverdrup, Sinha, Goodson et al.,
Applied Physics Letters 78 (2001)

Model: Sinha, Pop, Dutton, Goodson,
J. Heat Transfer (2006)

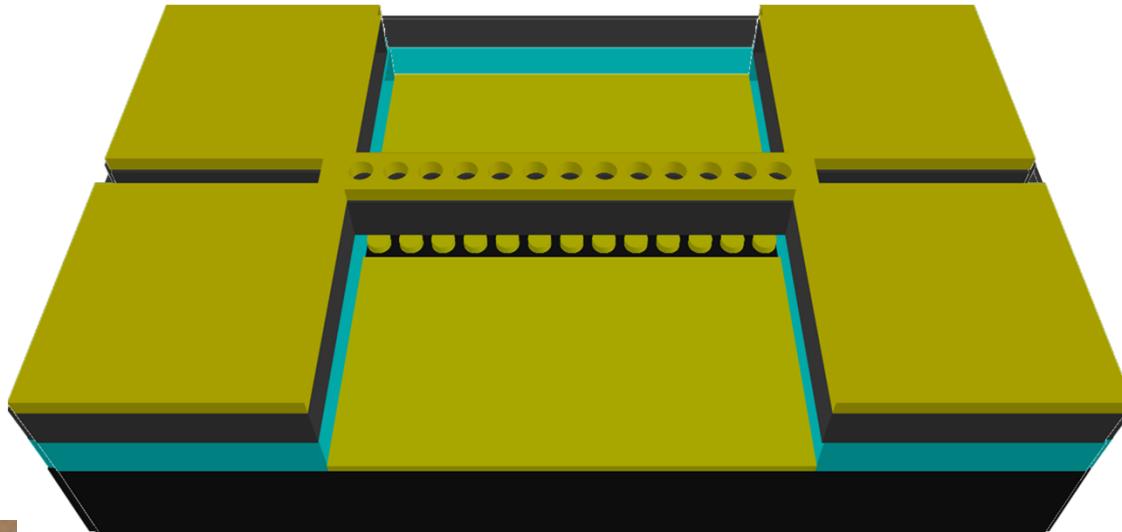


SOI-Enabled Phonon Studies

2010- (boundaries & nanoholes)



Nanoladder Device Fabrication



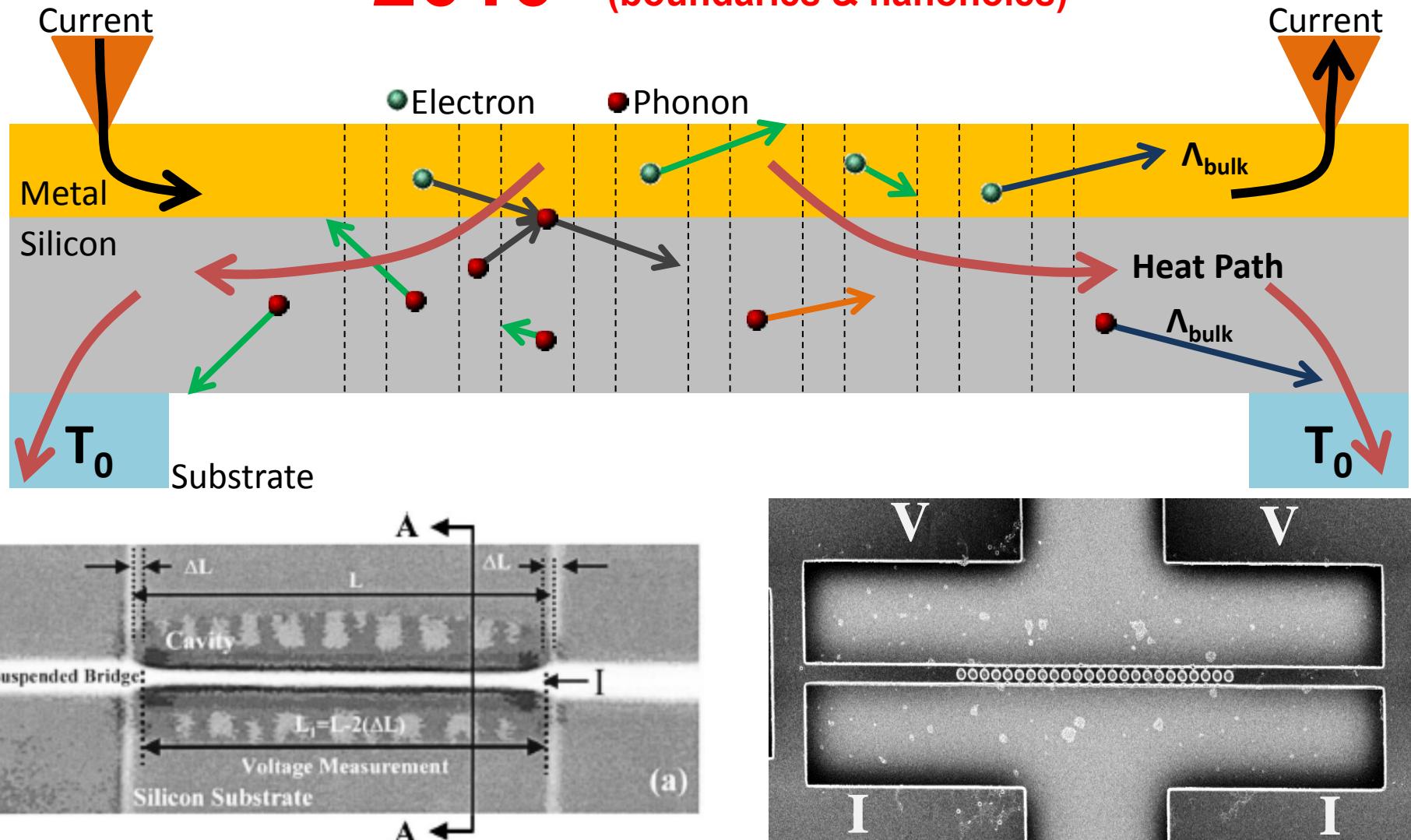
Dr. Taka Kodama

STANFORD
nanoheat

1. Silicon-On-Insulator Wafer
2. Deposit & Pattern (E-Beam Lithography) Photoresist
3. DRIE Etch Silicon Device Layer
4. Remove Oxide Layer To Suspend Device
5. Deposit Palladium Film

SOI-Enabled Phonon Studies

2010- (boundaries & nanoholes)

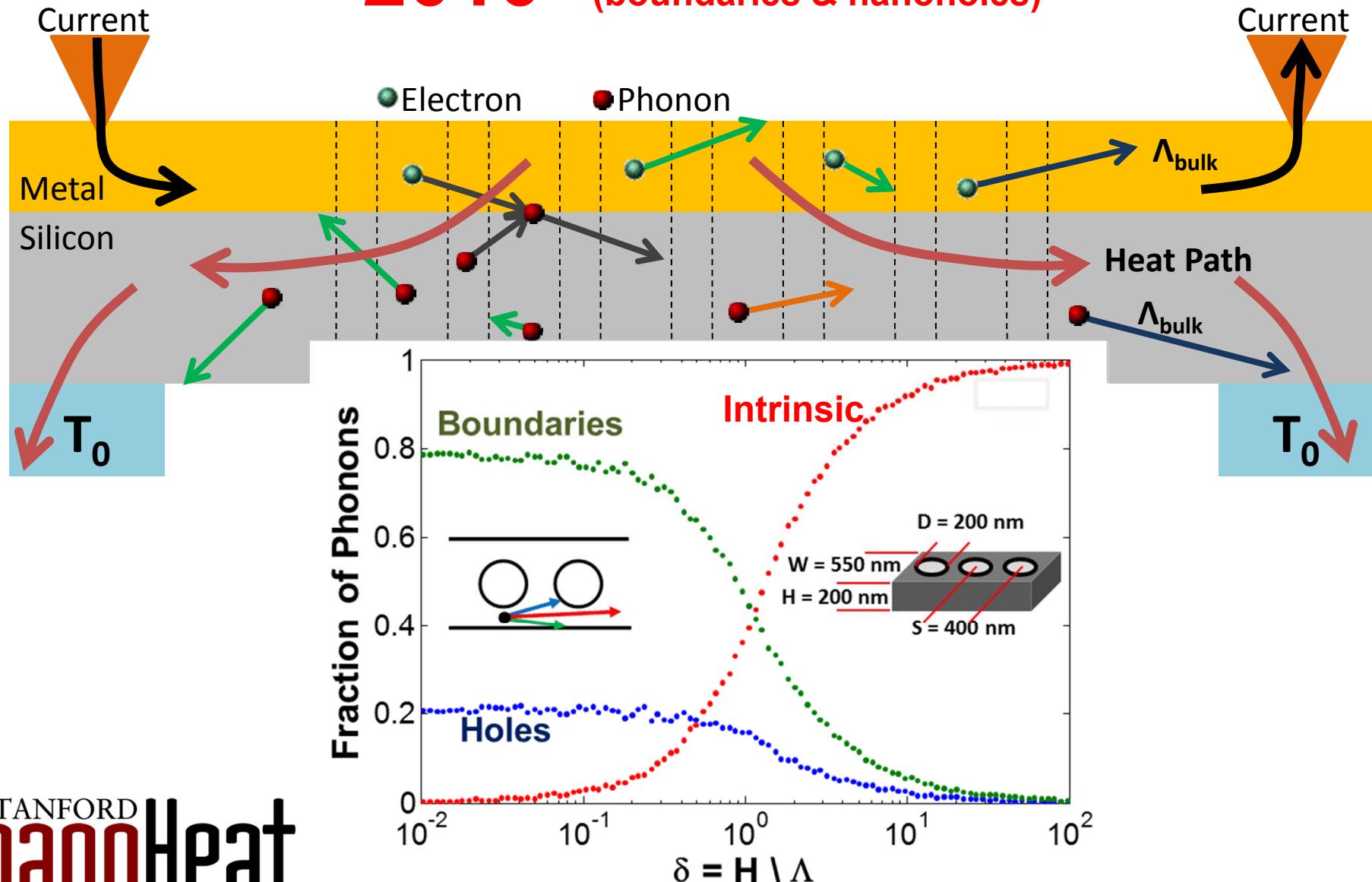


Liu and Asheghi
Applied Physics Letters (2004)

Marconnet, Kodama, Asheghi, Goodson, et al.
Nano & Microscale Thermophys. Eng. (2012)

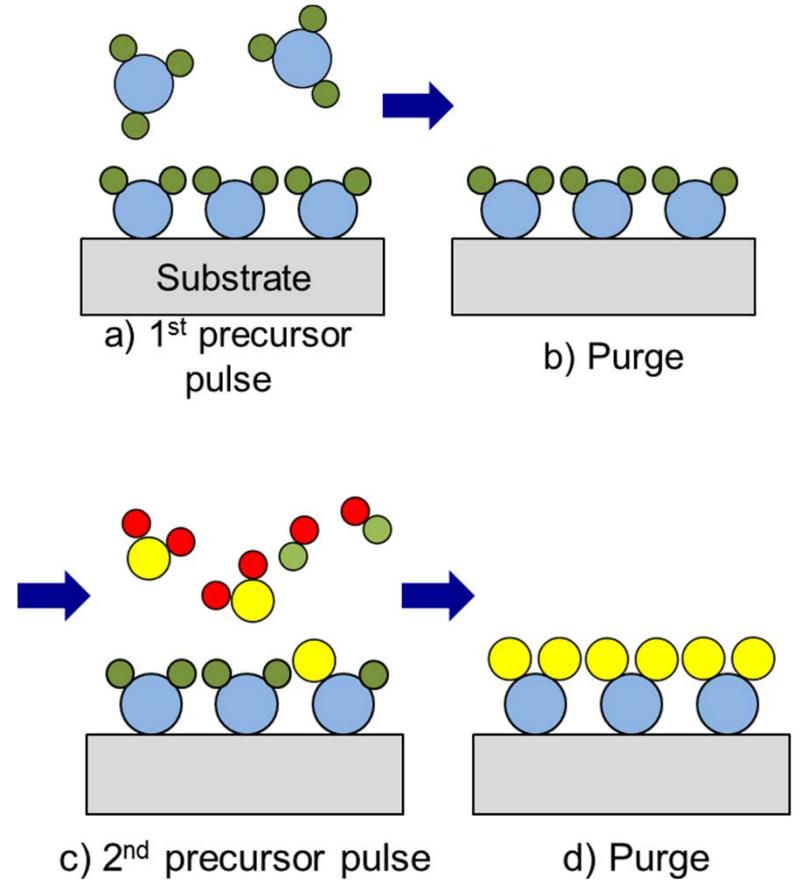
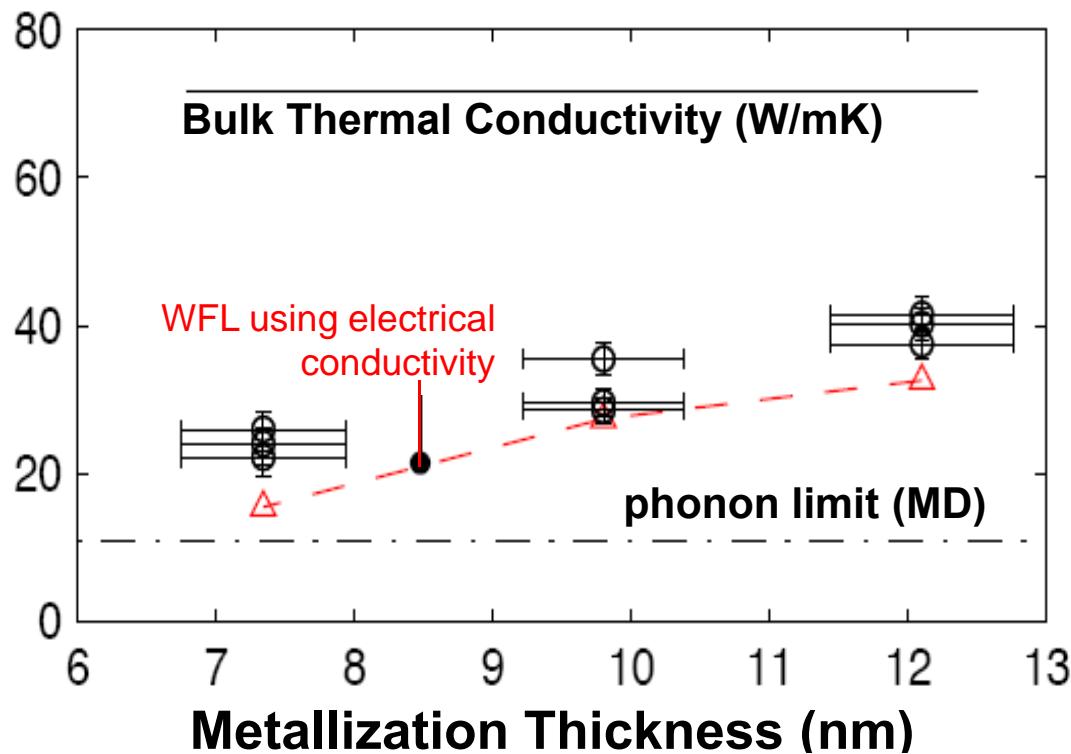
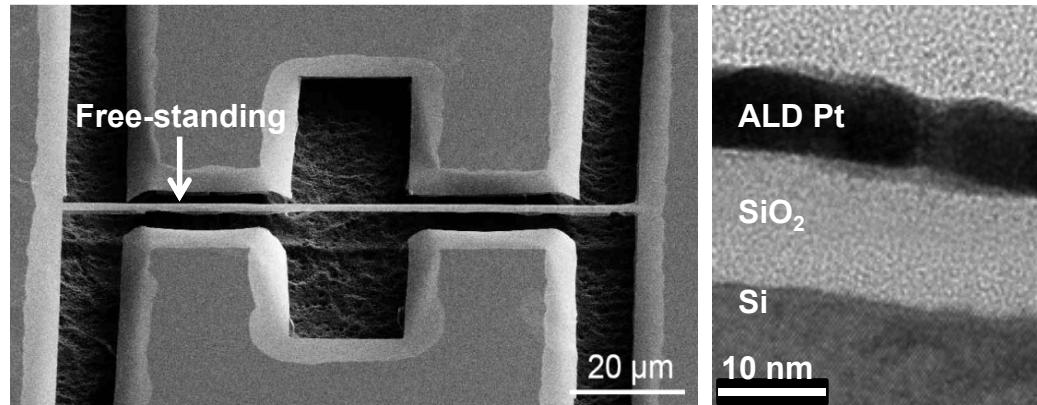
SOI-Enabled Phonon Studies

2010- (boundaries & nanoholes)

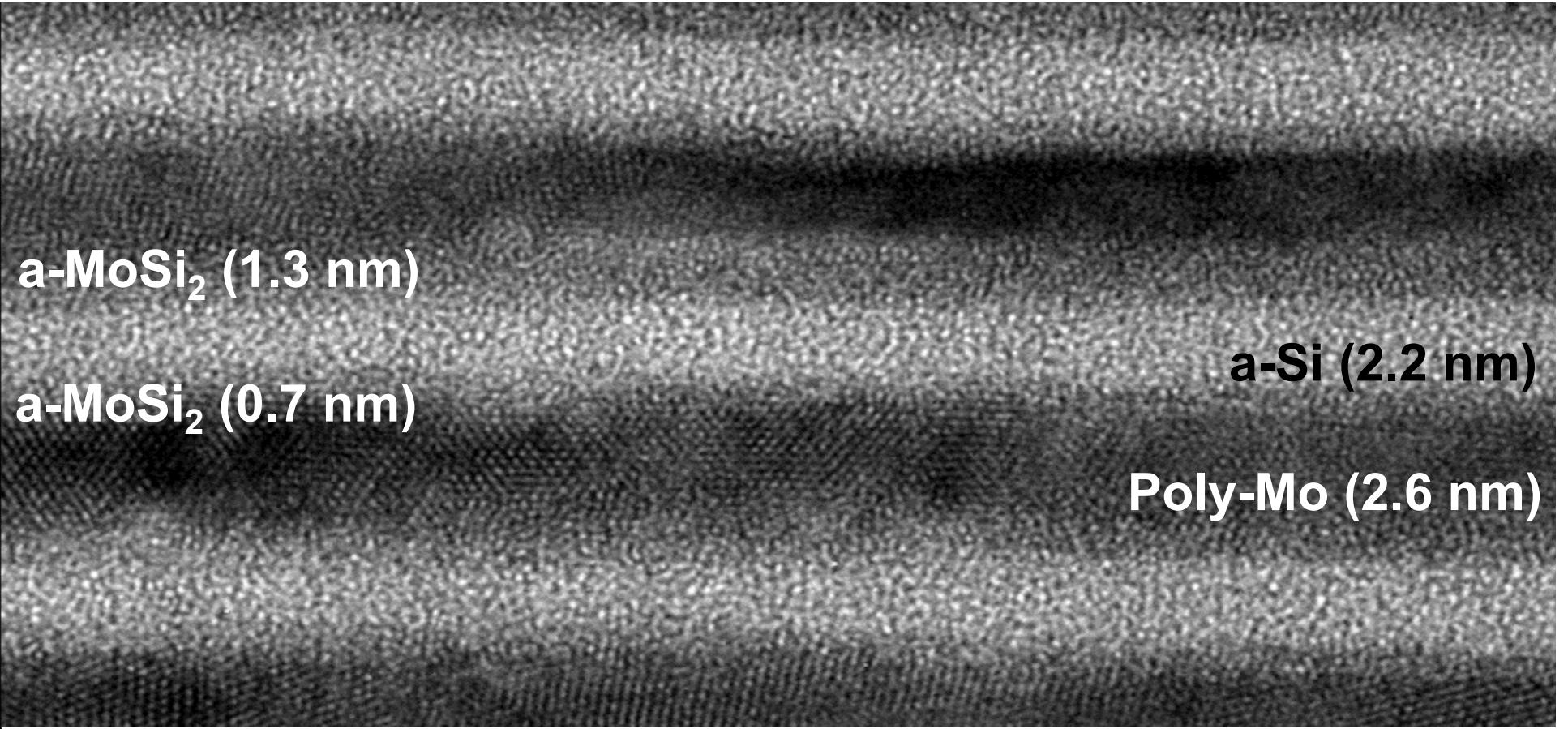


Probing the WFL at 7 nm

Yoneoka, Lee, Goodson, Kenny, et al., *Nano Letters* (2012)



Atomic Layer Deposition



NANO
LETTERS

Letter

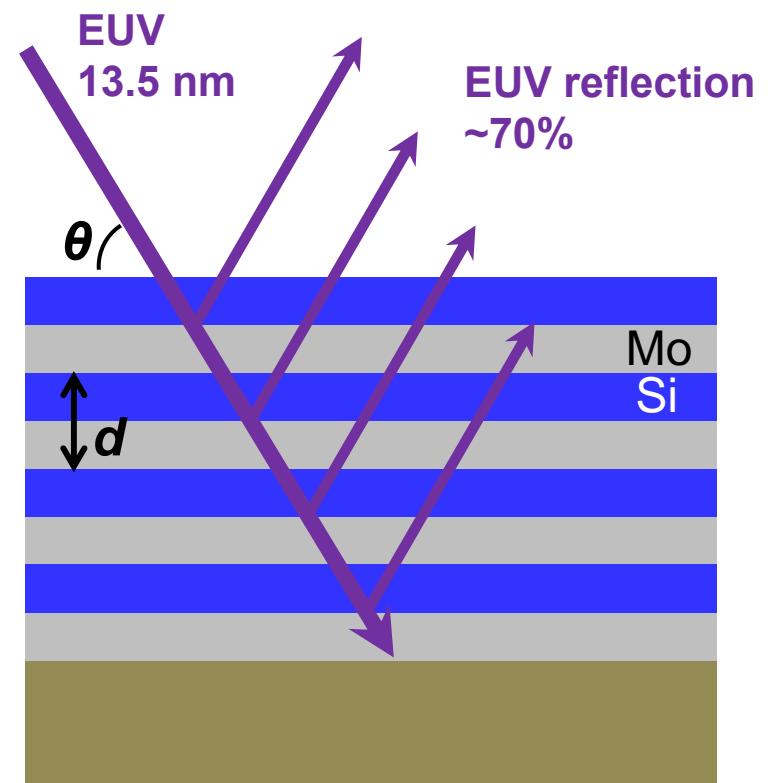
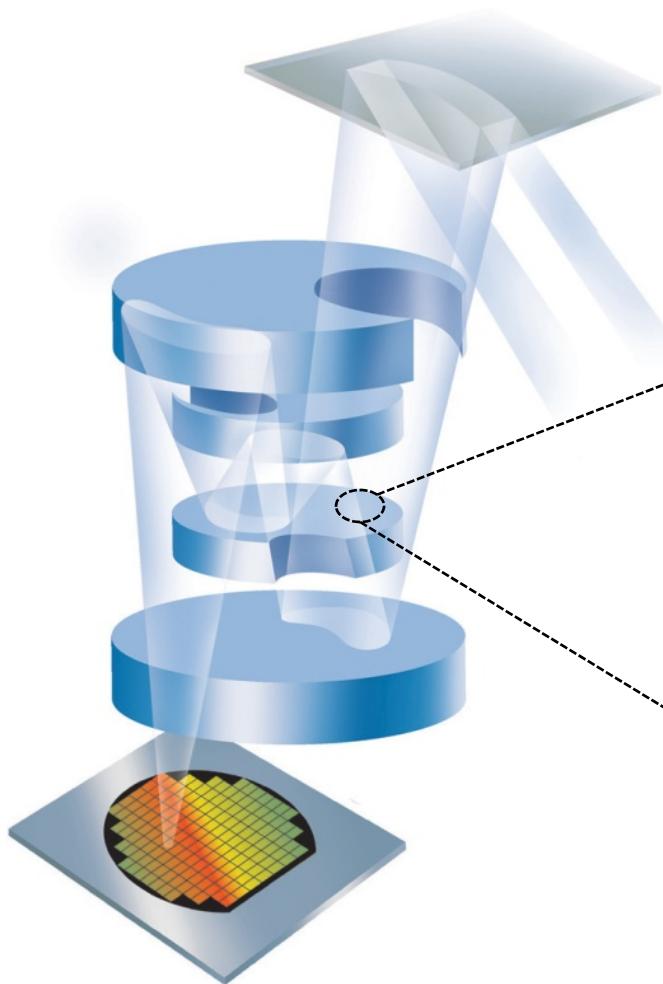
pubs.acs.org/NanoLett

Phonon Dominated Heat Conduction Normal to Mo/Si Multilayers with Period below 10 nm

Zijian Li,[†] Si Tan,[†] Elah Bozorg-Grayeli,[†] Takashi Kodama,[†] Mehdi Asheghi,[†] Gil Delgado,
Matthew Panzer,[†] Alexander Pokrovsky,[†] Daniel Wack,[†] and Kenneth E. Goodson*,[†]

KLA Tencor

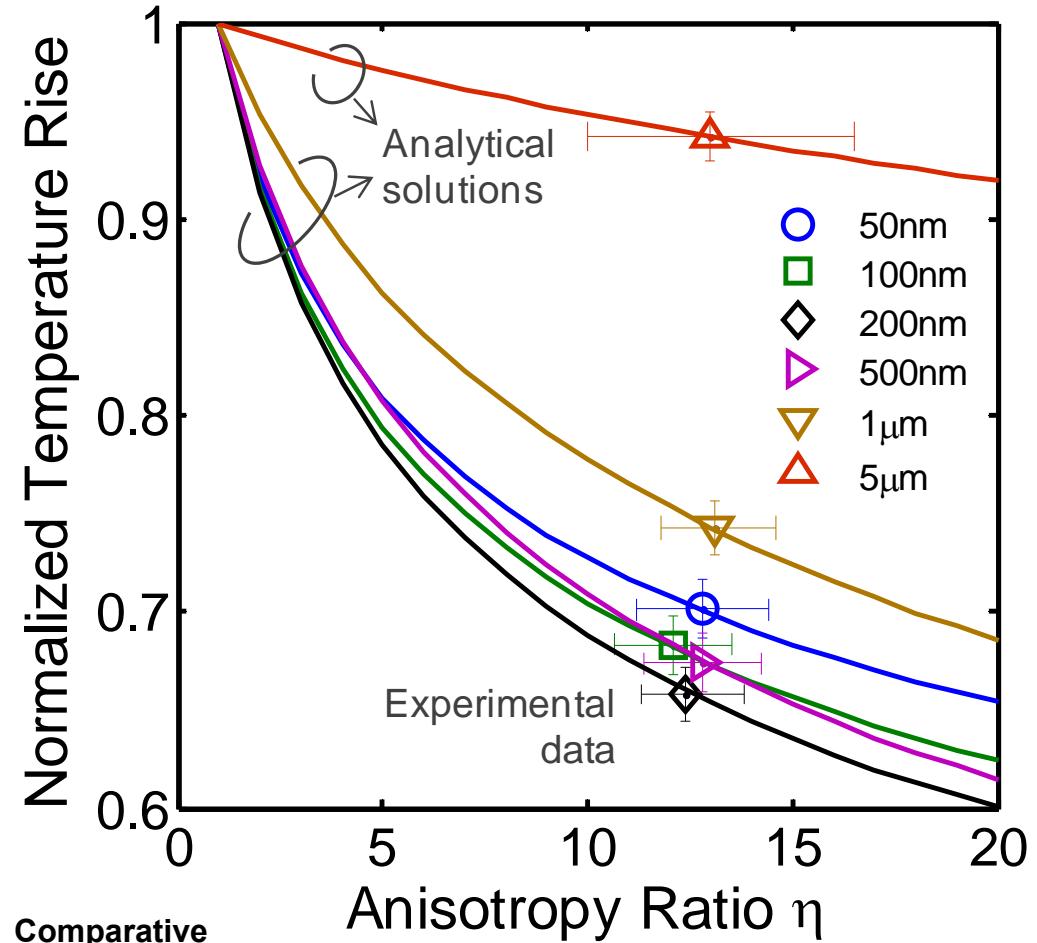
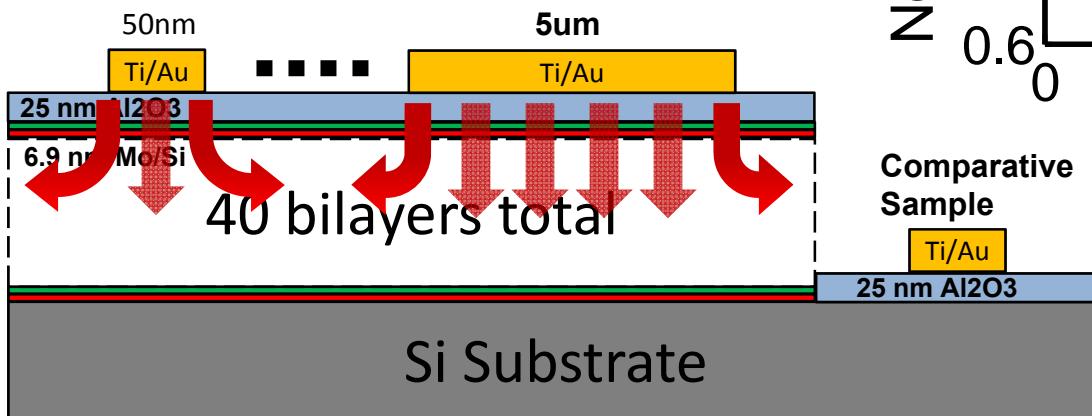
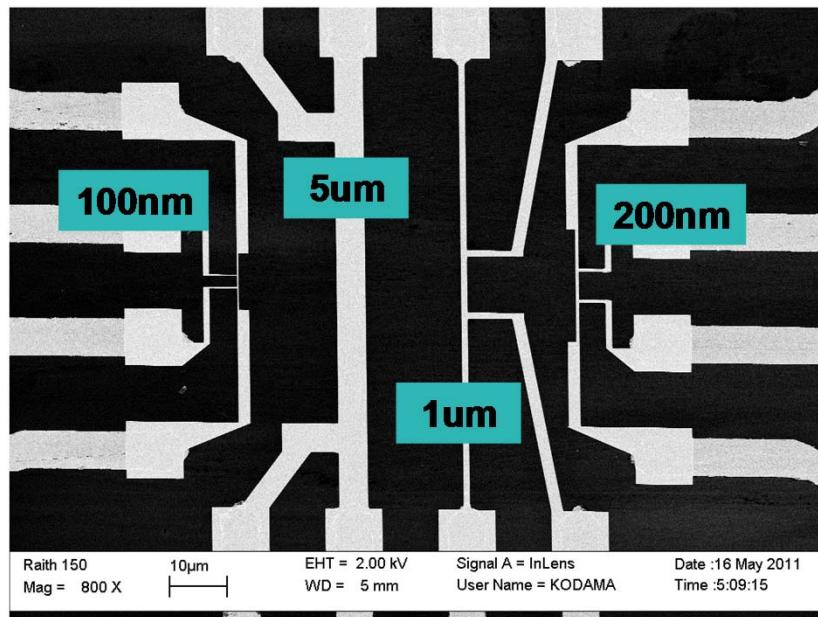
Extreme UV Optics



Carl Zeiss AG

Electrons & Phonons in Metal NanoLayers

Li, Goodson, et al., *Nano Letters* (2012), accepted and in press
Bozorg-Grayeli, Li, Goodson, et al., *Applied Physics Letters* (2011)



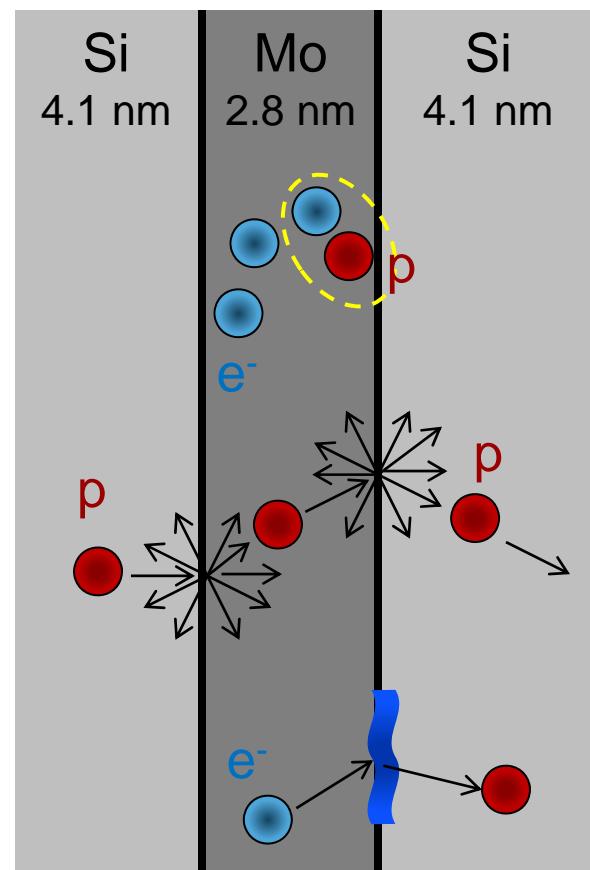
$$d_{\text{Mo}} = 2.8 \text{ nm}, d_{\text{Si}} = 4.1 \text{ nm},$$
$$k_{\text{Mo}} \sim 14 \text{ W/mK (WFL)}$$

Electrons & Phonons in Metal NanoLayers

Li, Goodson, et al., *Nano Letters* (2012), accepted and in press
Bozorg-Grayeli, Li, Goodson, et al., *Applied Physics Letters* (2011)

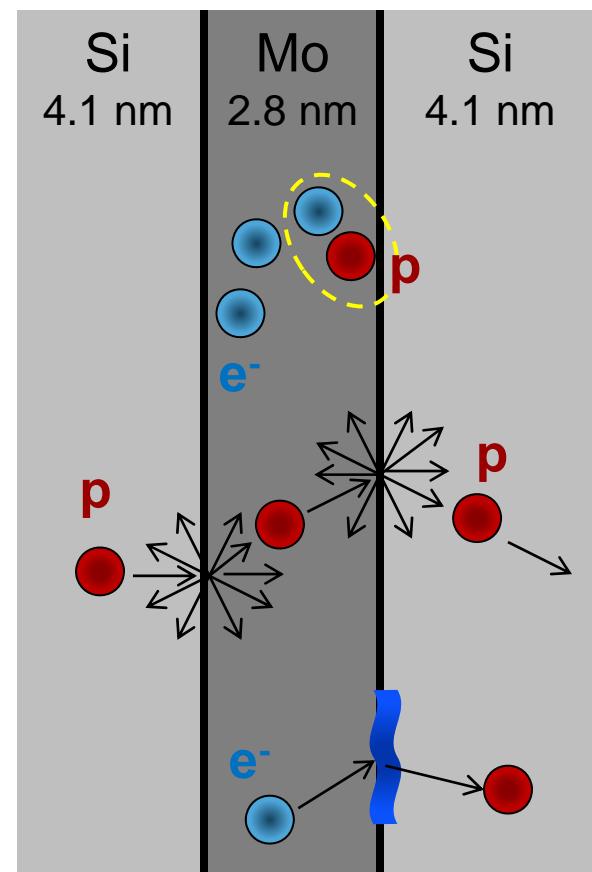
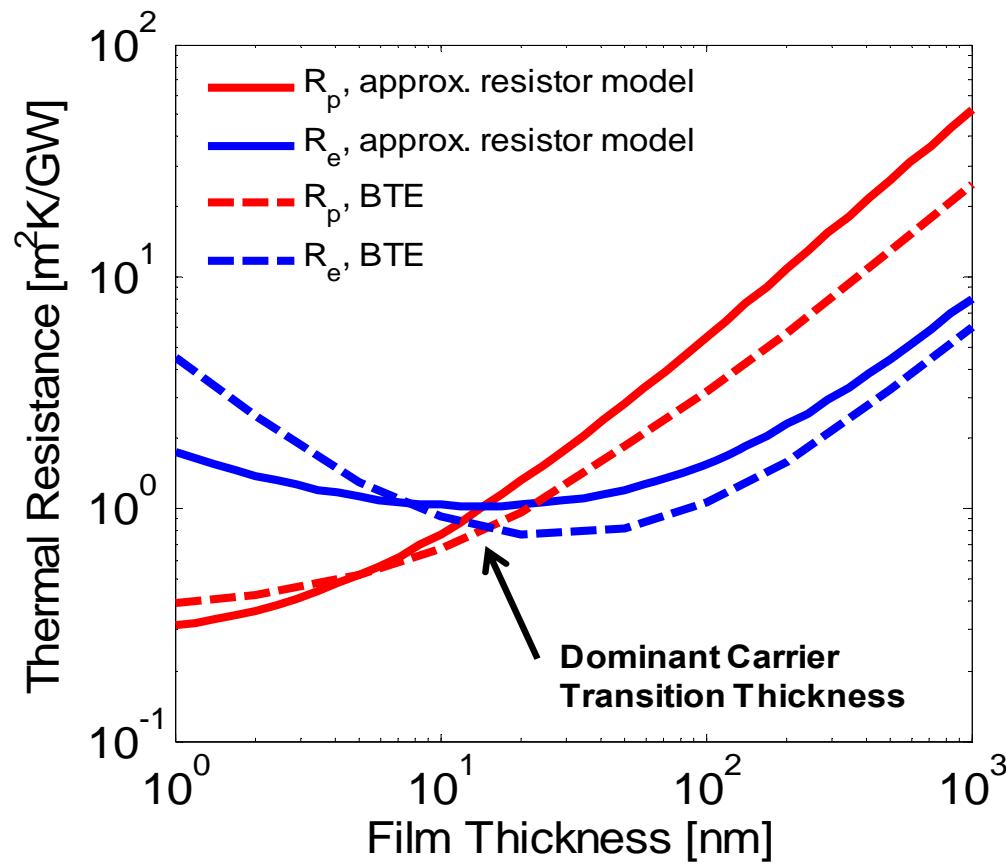
Anisotropy caused by:

- Series vs parallel film resistances
 $\eta = 2-3$
- Discrete interface resistances and ballistic electrons, $\eta = 4-9$
- Disorder and material interdiffusion at interfaces (smudging)
- Weak electron-phonon coupling and ballistic phonons?



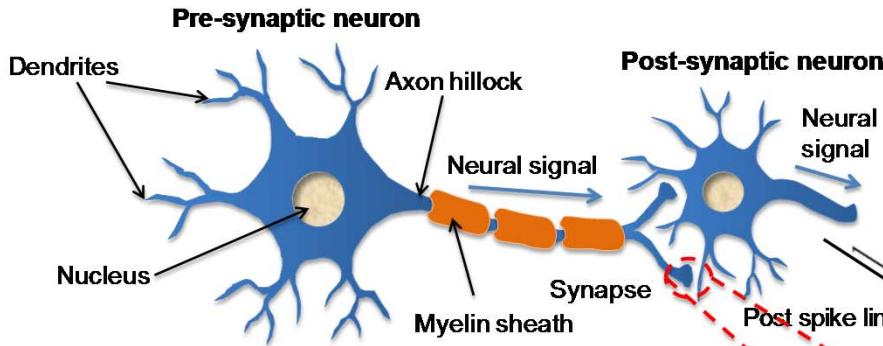
Electrons & Phonons in Metal NanoLayers

Li, Goodson, et al., *Nano Letters* (2012), accepted and in press
Bozorg-Grayeli, Li, Goodson, et al., *Applied Physics Letters* (2011)

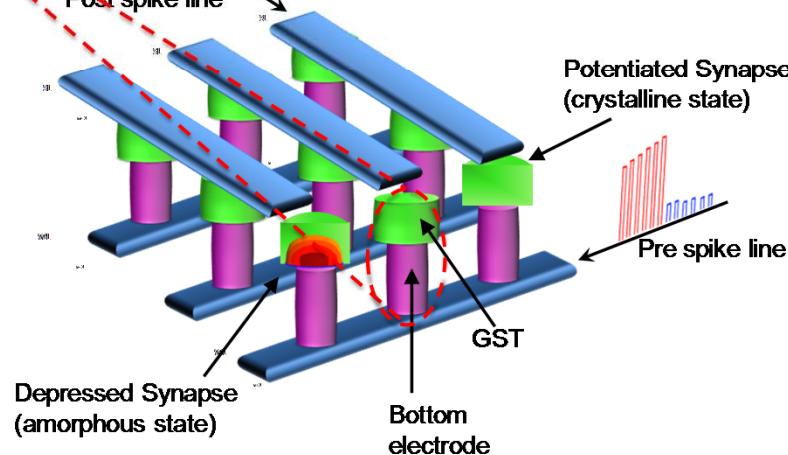


$$d_{trans} = 2k_p k_e / \left[\sqrt{Gk_p} (k_e - k_p) \right]$$

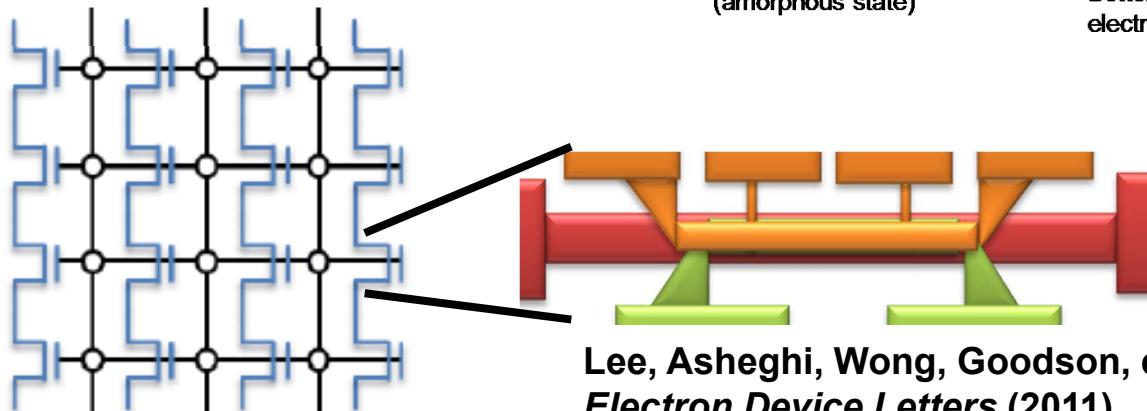
Future Phase Change Nanodevices



Synapses for Brain-Inspired Computing
Kuzum, Jeyasingh, Lee, Wong,
Nano Letters (2011)



Field-Programmable Gate Arrays



Lee, Asheghi, Wong, Goodson, et al.
Electron Device Letters (2011)

RF-FPGA

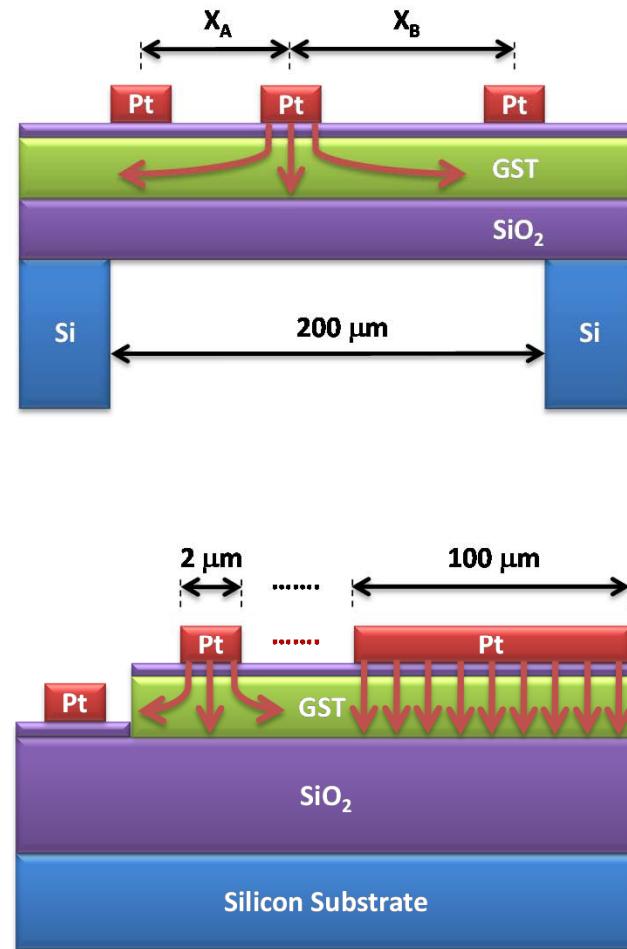
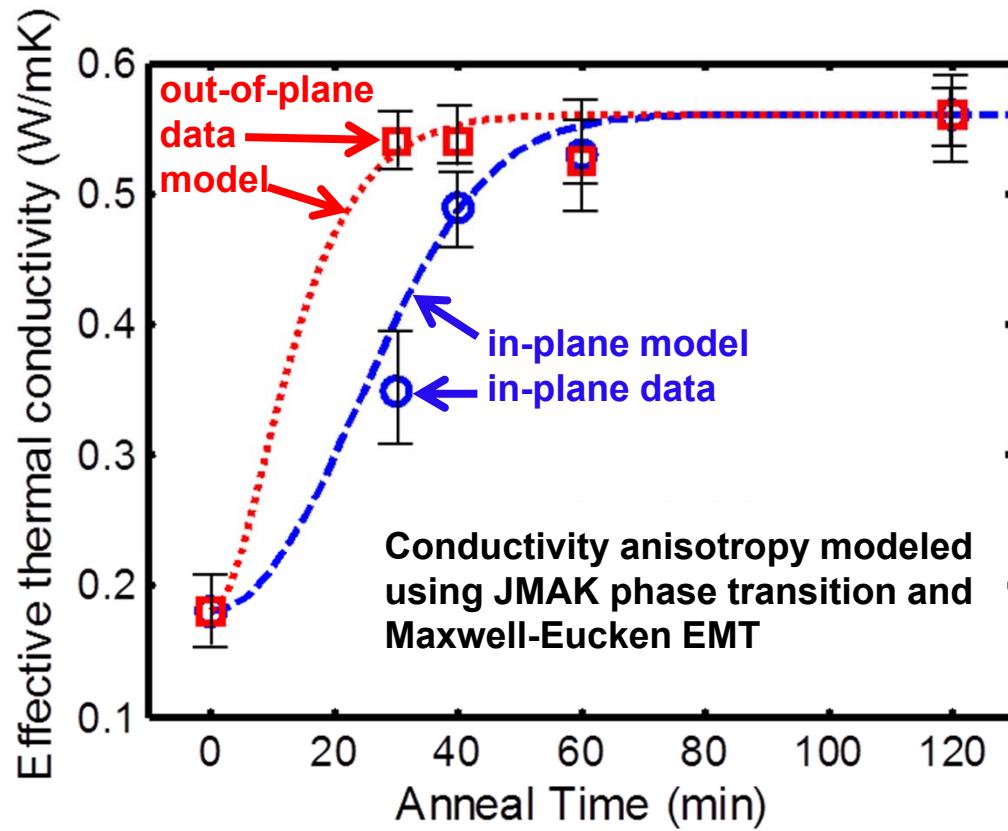


SyNAPSE

Phase Transition Complexity in $\text{Ge}_2\text{Sb}_2\text{Te}_5$

Lee, Li, Sinclair, Goodson, et al., Journal of Applied Physics (2011)

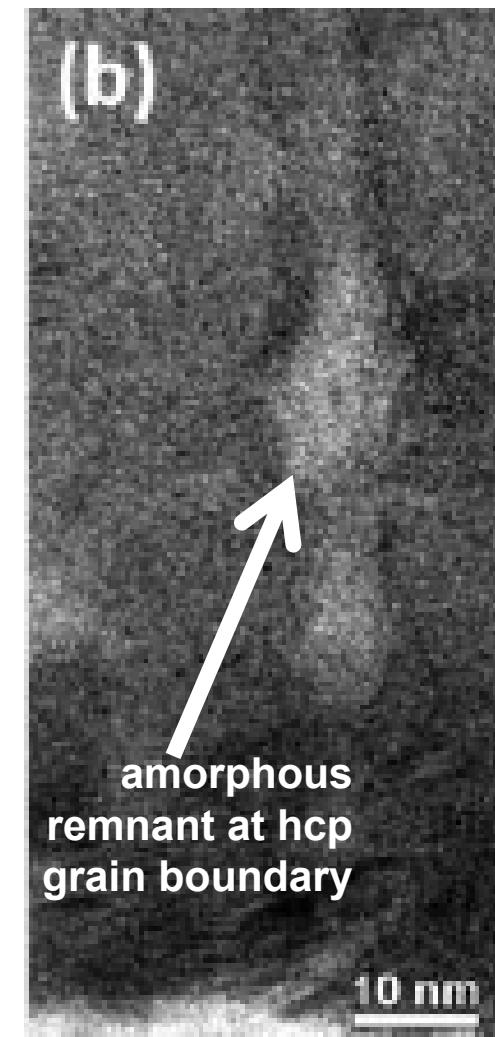
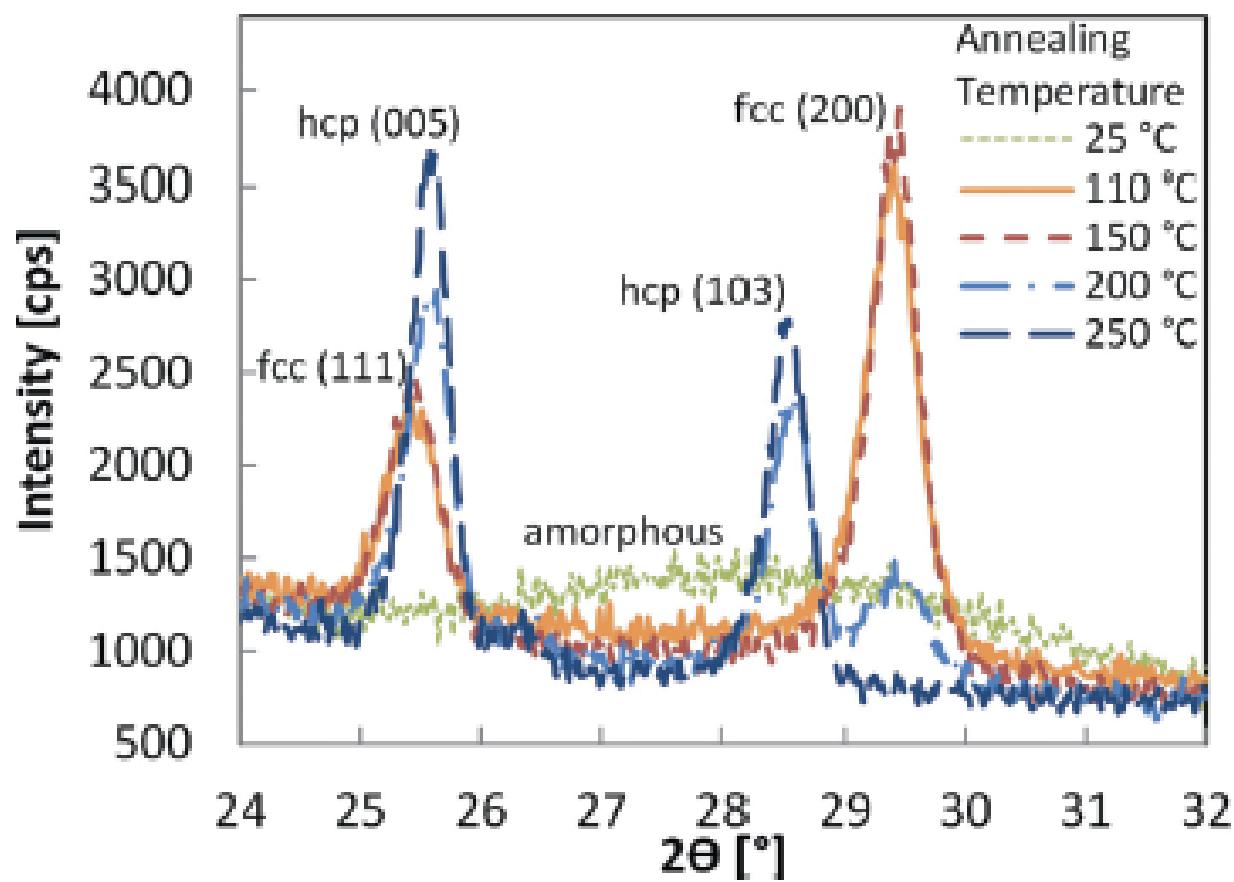
Li, Lee, Wong, Goodson et al., Electron Device Letters (2011)



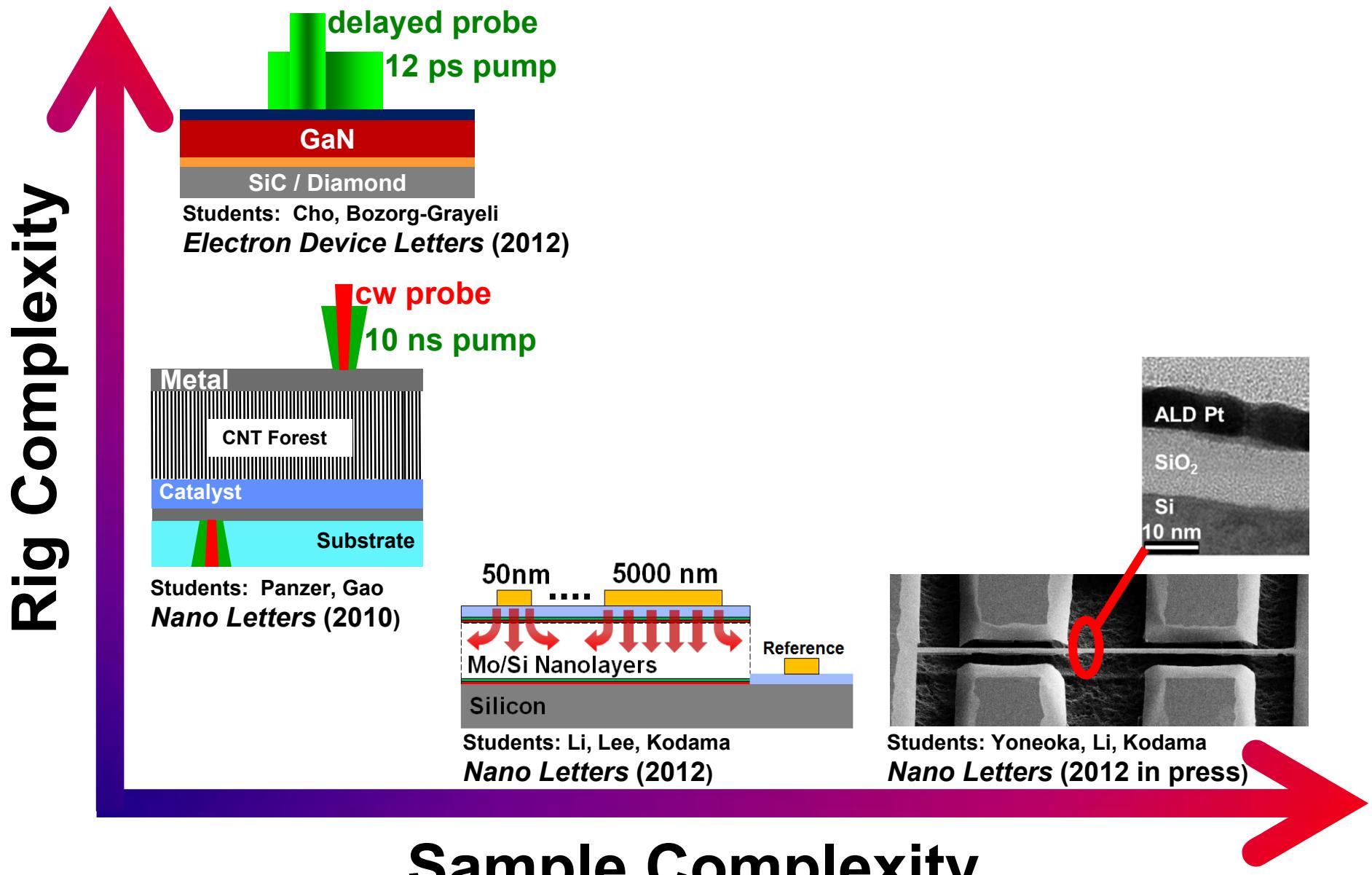
Phase Transition Complexity in $\text{Ge}_2\text{Sb}_2\text{Te}_5$

Lee, Li, Sinclair, Goodson, et al., Journal of Applied Physics (2011)

Li, Lee, Wong, Goodson et al., Electron Device Letters (2011)



Nano Thermal Metrology

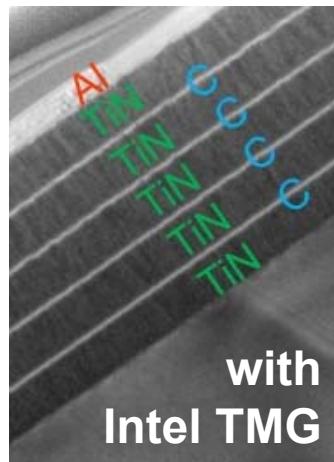


TDTR/TTR Sample Design

Phase Change Interfaces

Students: Bozorg-Grayeli, Li, Reifenberg

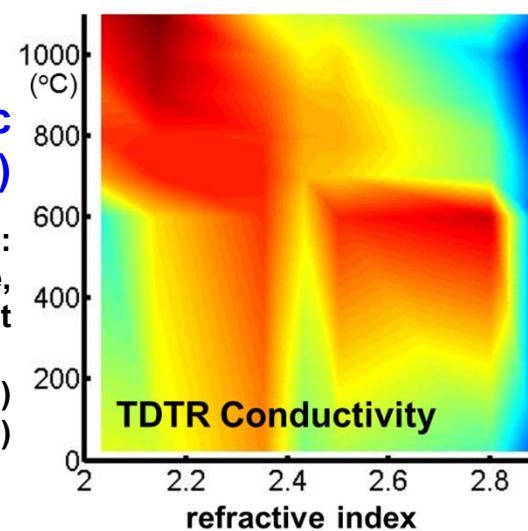
Applied Physics Letters (2007)
Electron Device Letters (2008, 2010, 2011)



NanoPhotonic Crystals (SRO/SRN)

Students:
Rowlette, Kekatpure,
Marconnet

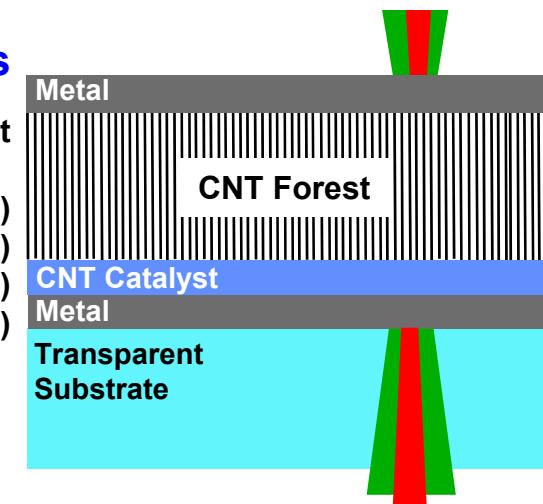
Physical Review B (2009)
Applied Physics Lett. (2012)



CNT Forests

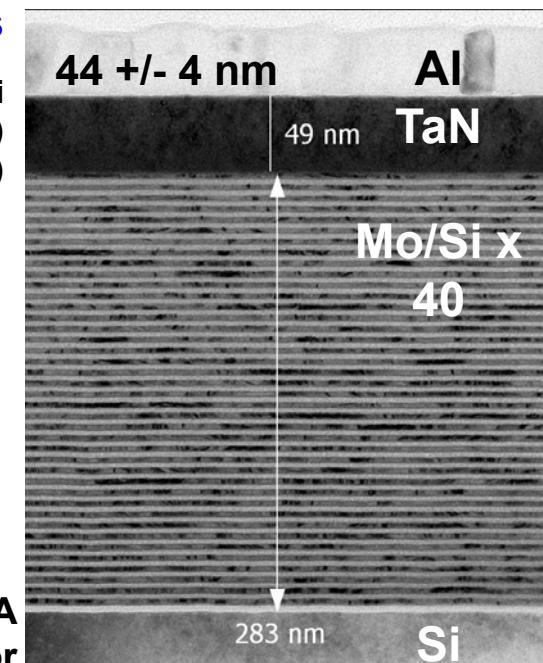
Students: Panzer, Gao, Marconnet

ACS Nano (2011)
Nanoletters (2010)
J. Heat Transfer (2008)
J. Electronic Materials (2009)

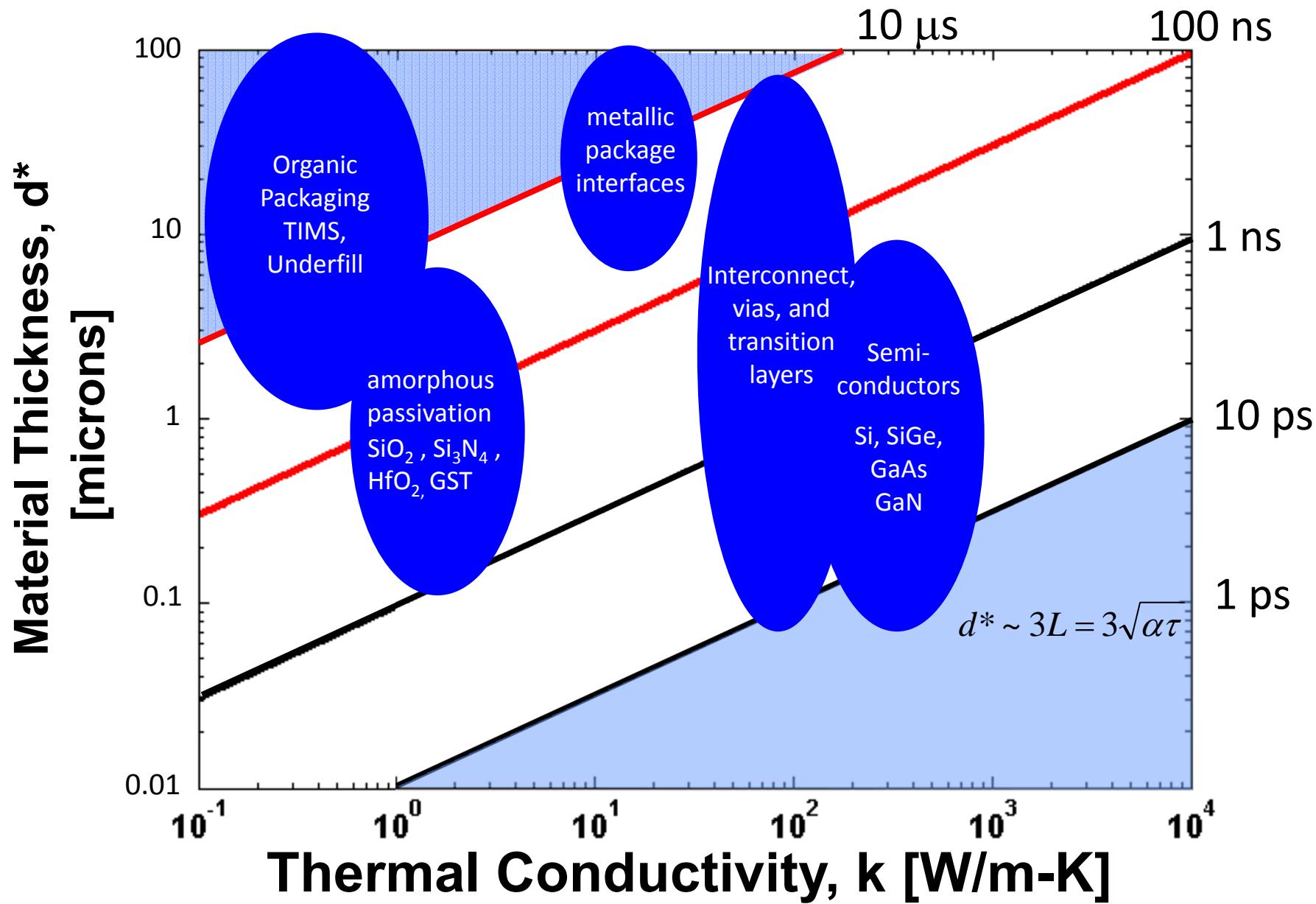


Extreme UV NanoOptics

Students: Bozorg-Grayeli, Li
Applied Physics Letters (2012)
Nano Letters (2012)



Required Measurement Timescales

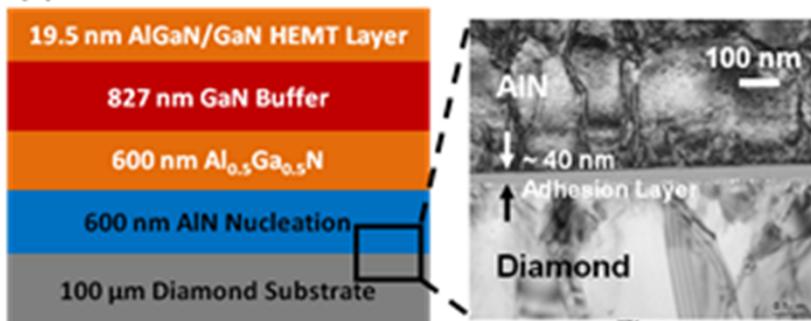


Diamond Composite Substrates

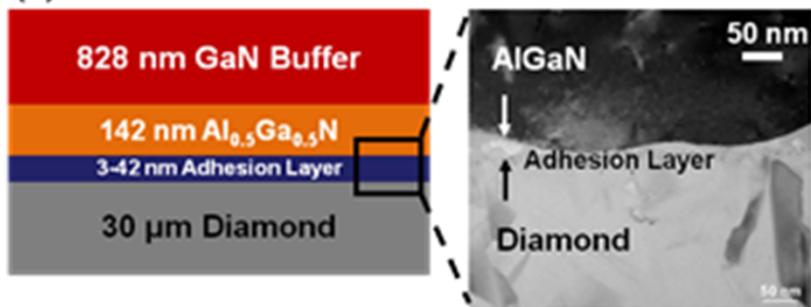
DARPA NJTT Programs

HEMT Composite Substrates

(a)

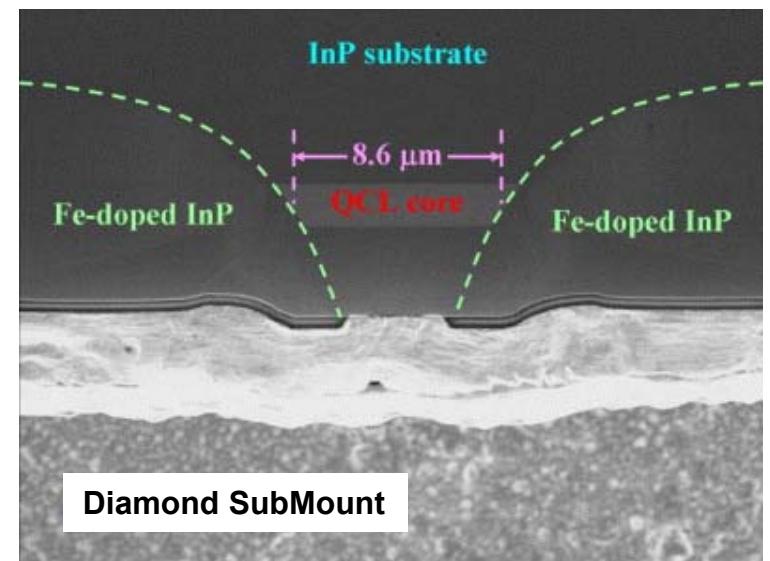


(b)



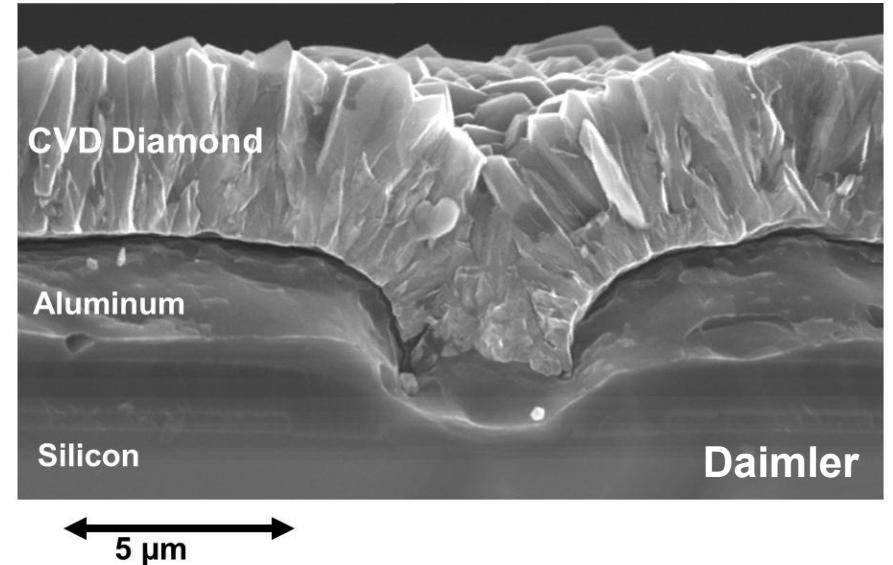
Proc. IITHERM 2012, with Group4 Labs

Quantum Cascade Laser SubMounts



Razeghi et al., *N. J. Phys.* (2009)

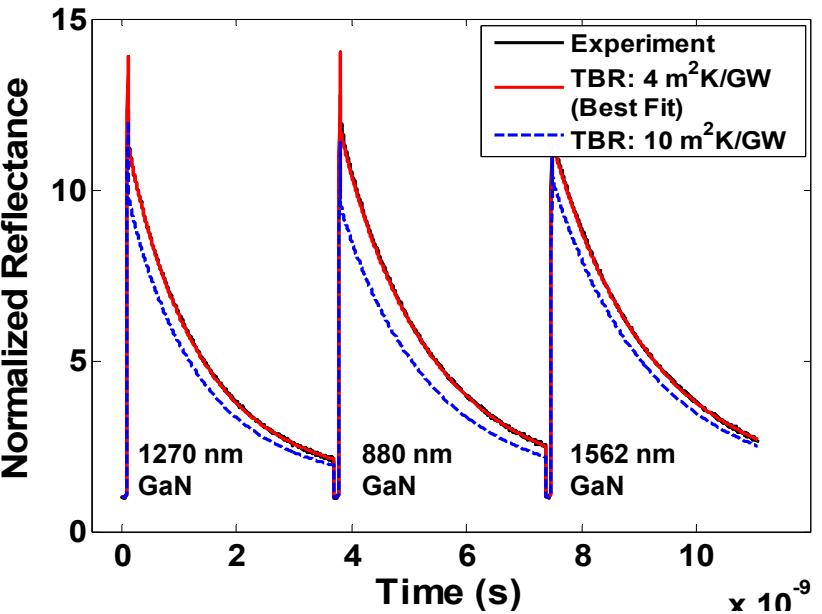
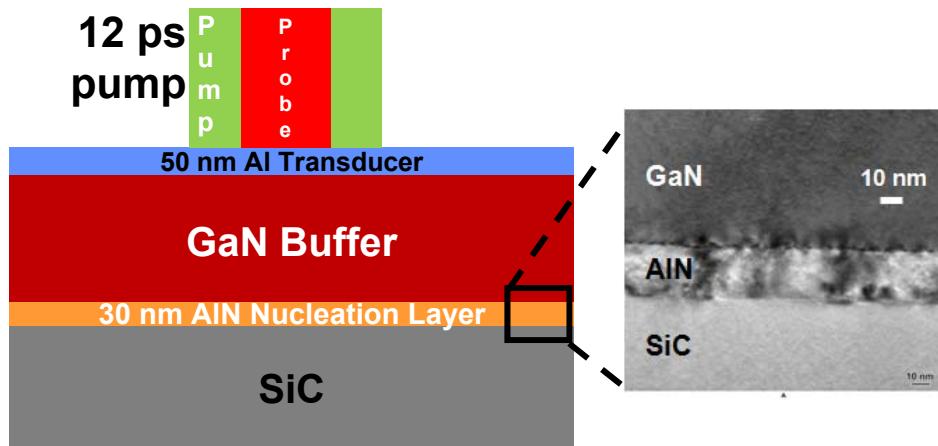
POWER FET Passivation



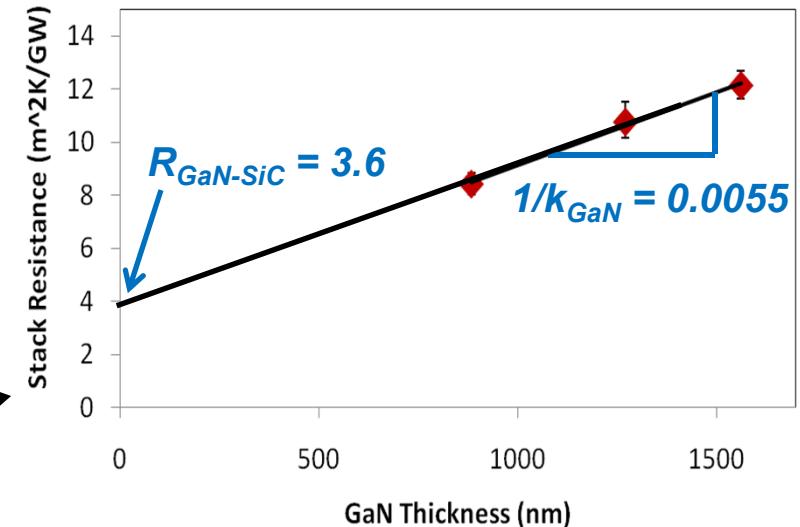
TDTR Boundary Resistance Extraction

Stanford with Raytheon: Cho, Altman, Asheghi, Goodson, *Electron Device Letters* (2012)

GaN Composite Substrates



Sample	k_{GaN} W/m/K	$R_{\text{GaN-SiC}}$ $\text{m}^2\text{K/GW}$	AlN thickness nm
Raytheon HEMT ps TDTR simul-fit	157 ± 11	4.2 ± 0.6	27
Raytheon HEMT extrapolation	182 ± 33	3.6 ± 1.6	27

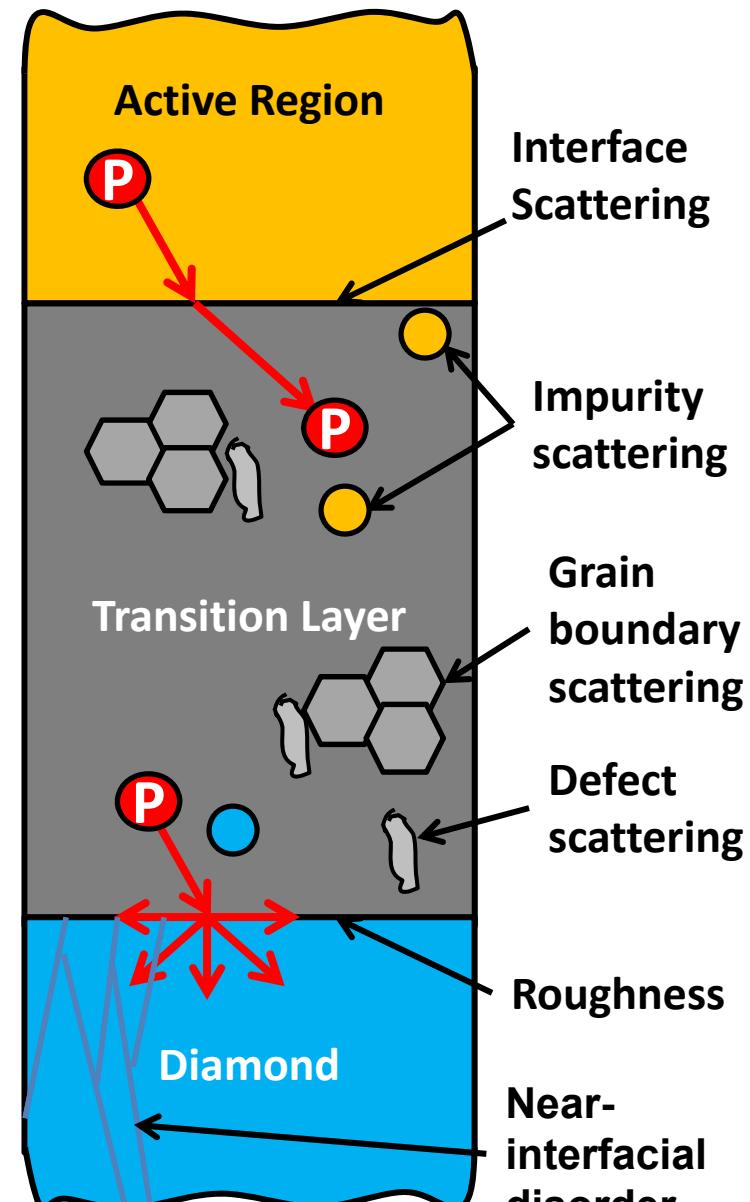


Thermal Resistance Mechanisms

Discrete carrier scattering at interfaces

Scattering on imperfections, stoichiometric impurities, and disorder in transition film

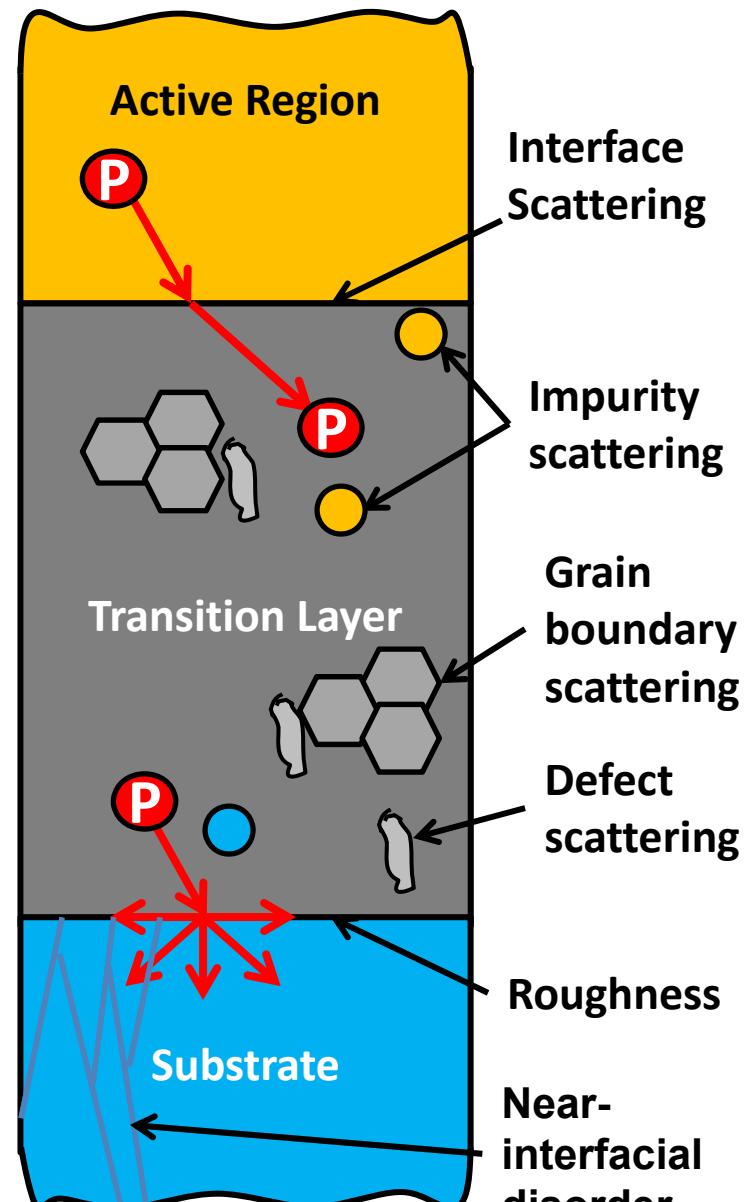
Near-interfacial disorder in primary composite substrate materials (GaN & Diamond)



Thermal Resistance Mechanisms

Discrete carrier scattering at interfaces

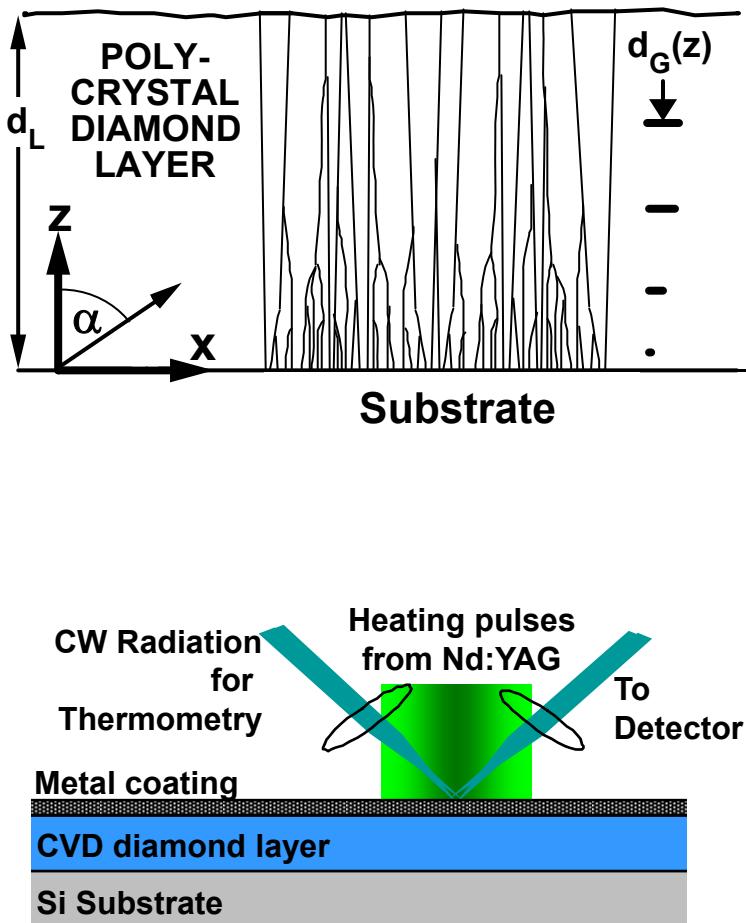
Scattering on imperfections, stoichiometric impurities, and disorder in transition film



Near-Interfacial Diamond

Touzelbaev & Goodson, *Diamond & Related Materials* (1998)
 Touzelbaev & Goodson, *J. Thermophysics & Heat Transfer* (1998)

Goodson, *ASME J. Heat Transfer* (1996)
 Goodson et al., *Journal of Applied Physics* (1995)

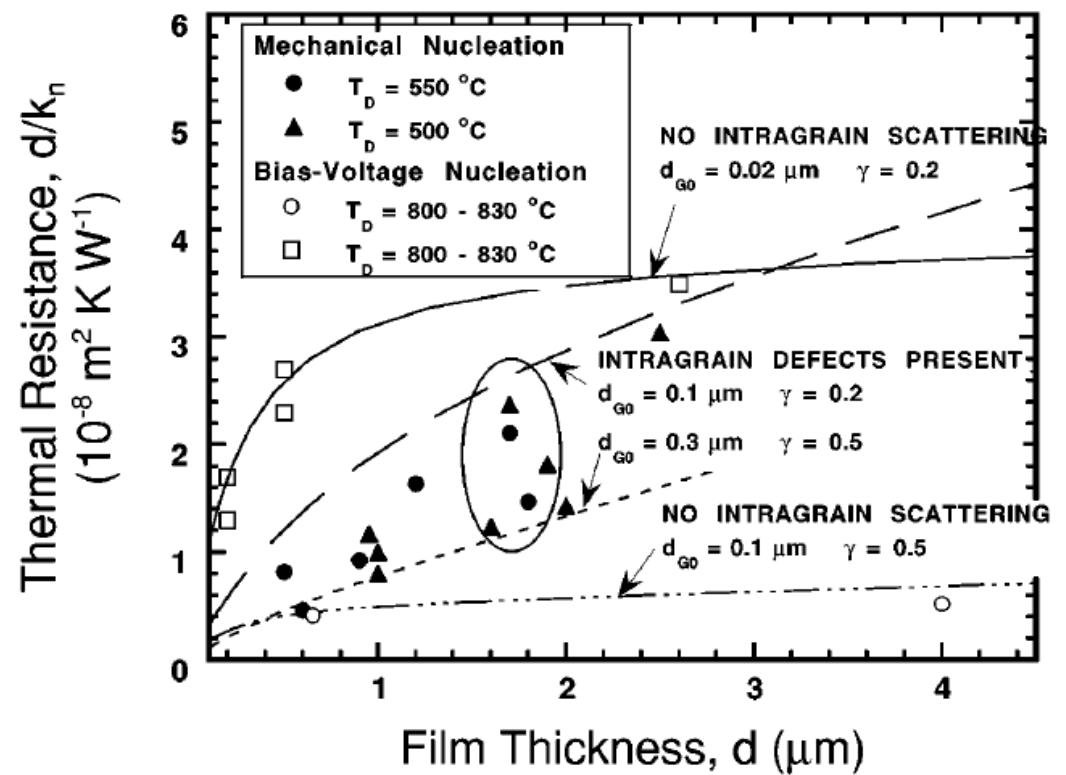


Mean free path

$$\Lambda^{-1} \cong \Lambda_{\text{phonon}}^{-1} + \Lambda_{\text{grain-boundary}}^{-1} \cong \Lambda_{\text{phonon}}^{-1} + \frac{d_G}{2\eta}$$

Grain-boundary scattering strength

$$\eta = \sum_{\text{defect types}} \sigma n(z)$$

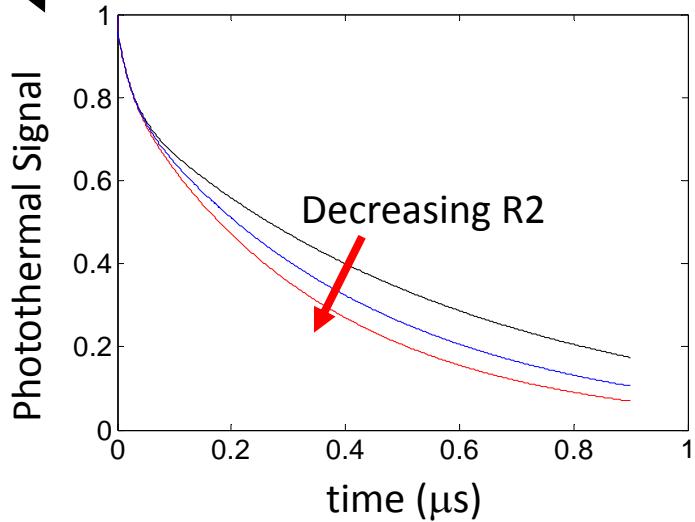
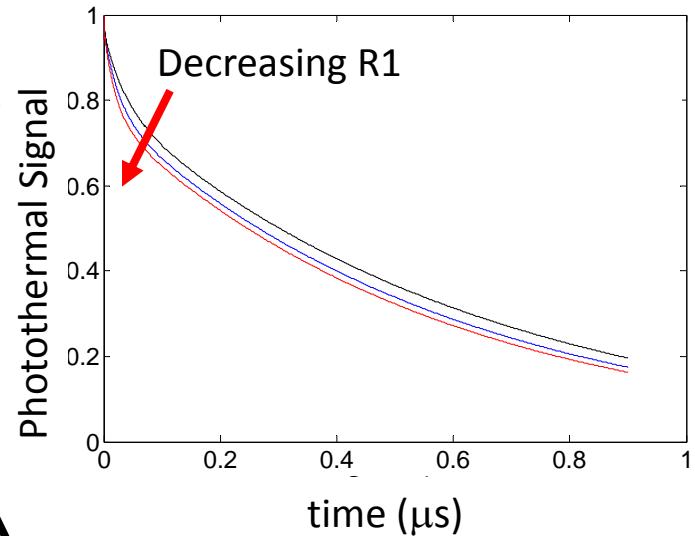
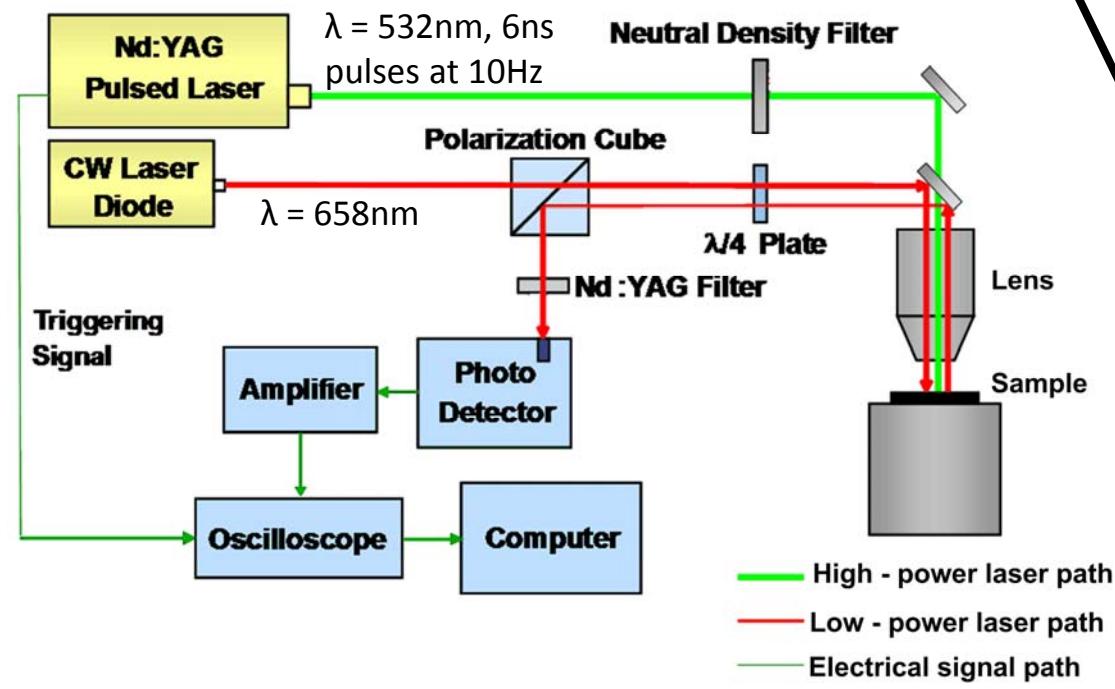
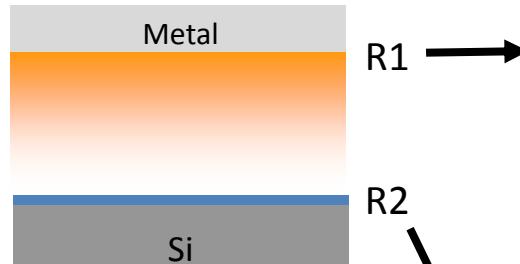


Nanosecond Thermoreflectance

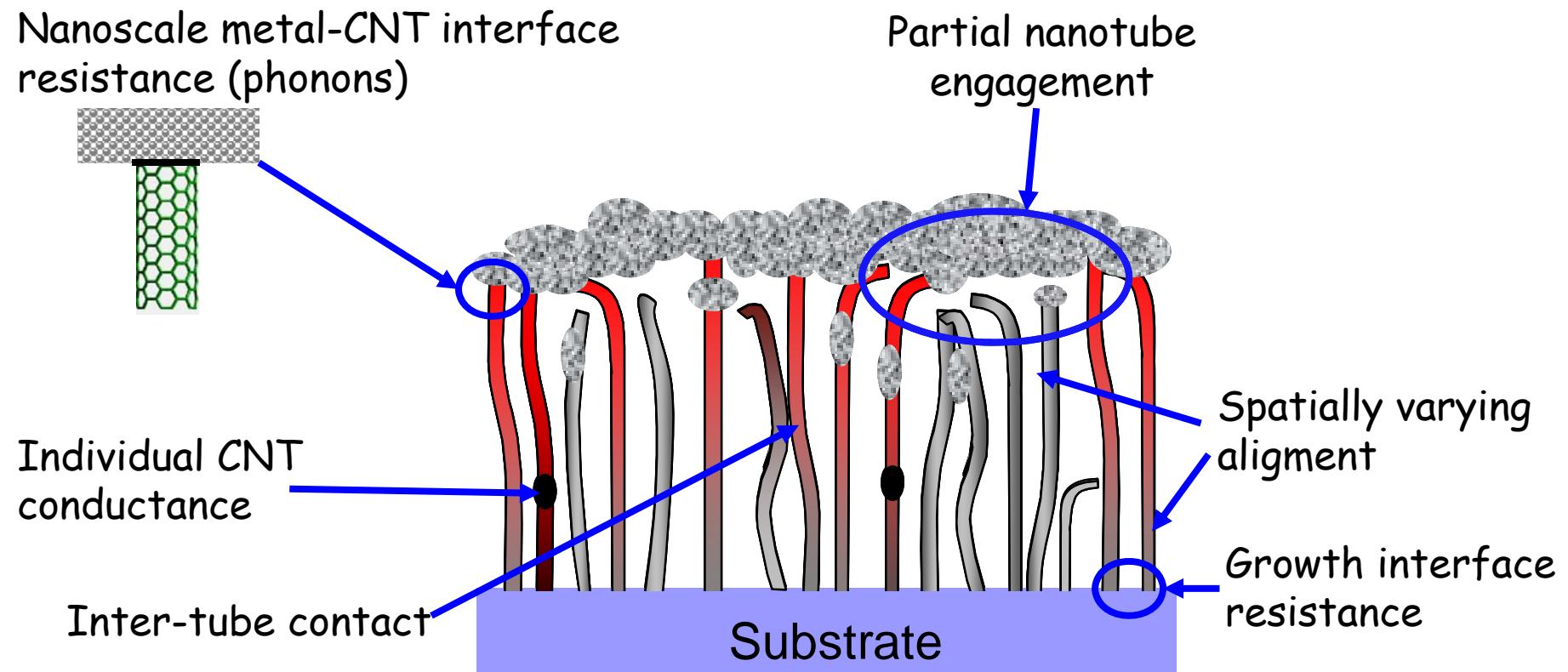
Panzer, Goodson, et al., *J. Heat Transfer* (2008), *NanoLetters* (2010)

Kaeding, Goodson, et al., *Applied Physics Letters* (1993)

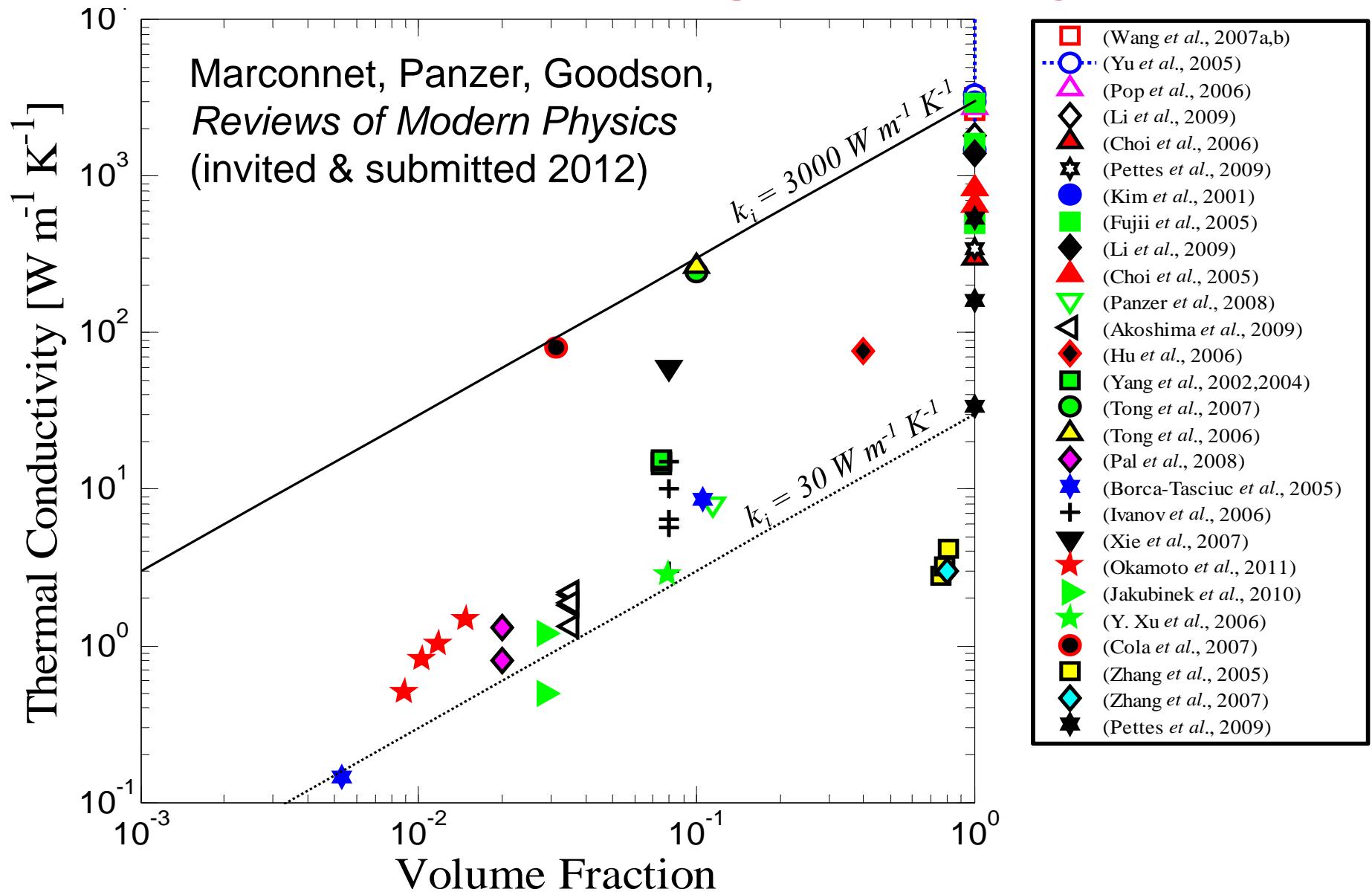
Rapid optical heating and thermometry allows vertical resistance contributions to be extracted independently



Conduction Physics in CNT Films

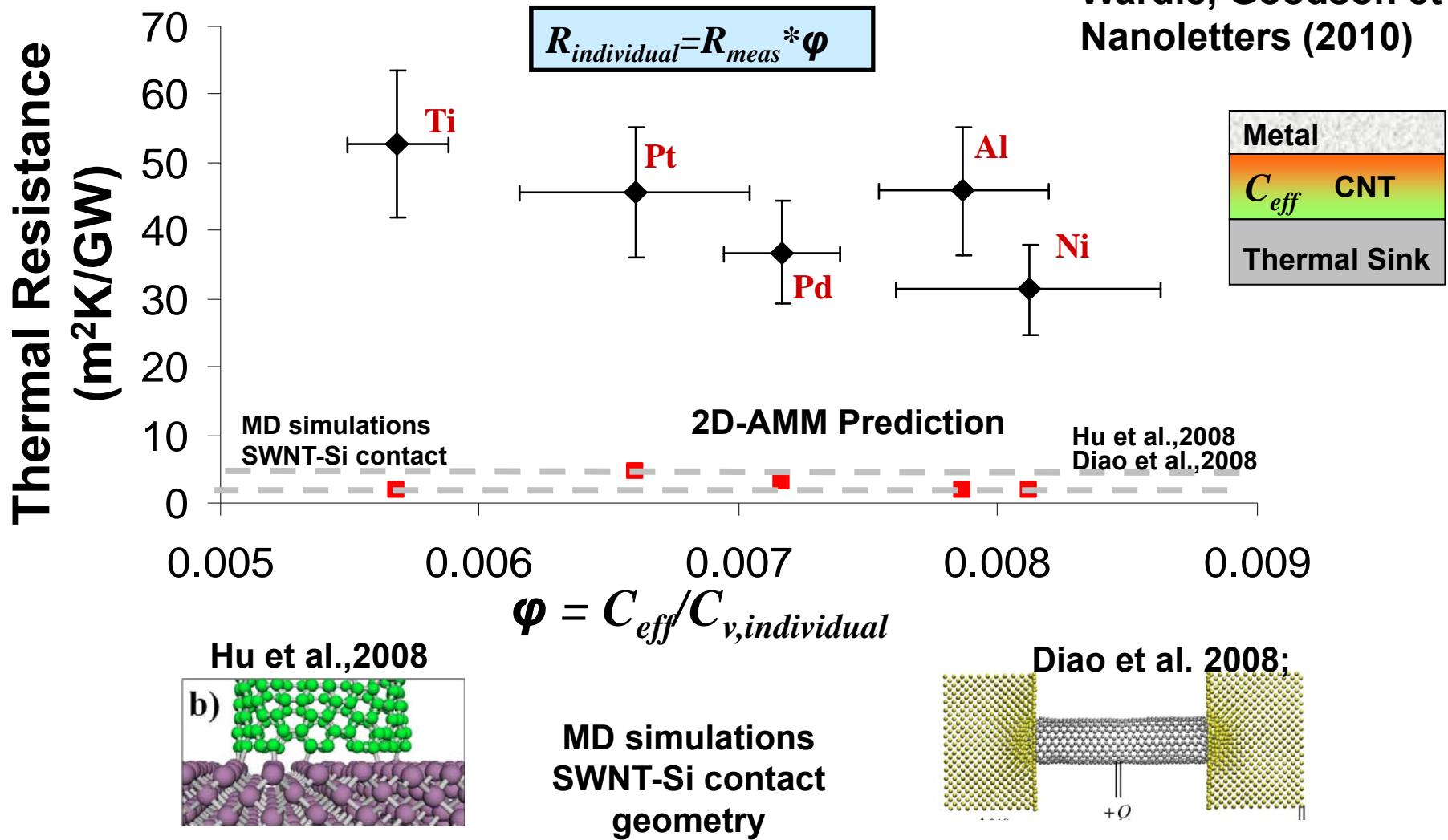


Thermal Conductivities of Individual CNTs and Aligned Arrays



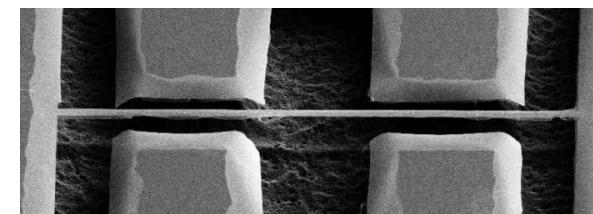
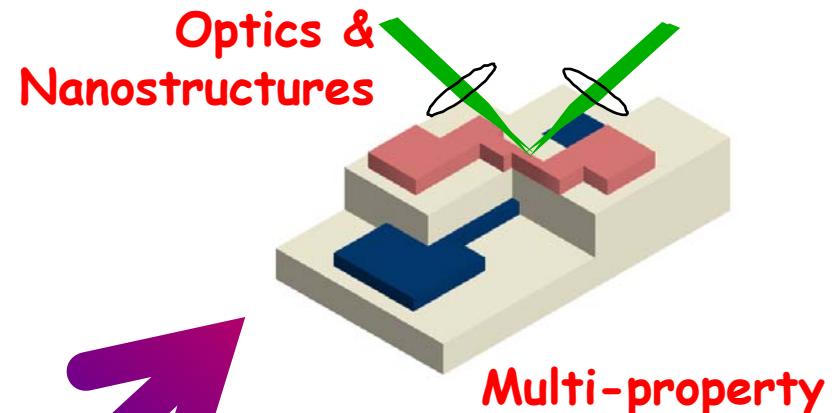
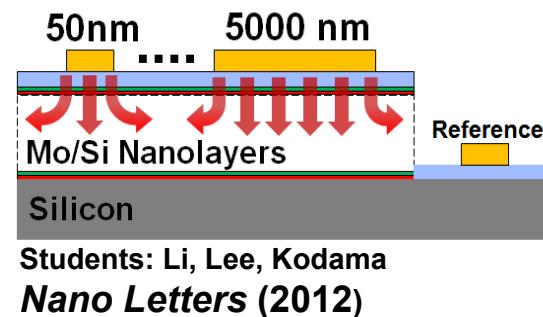
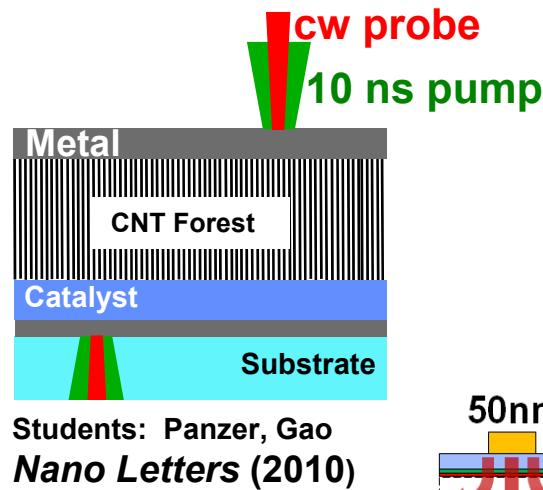
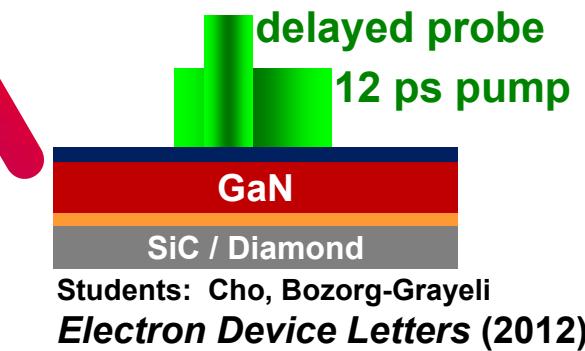
Data and Modeling for Individual SWNT-metal Interface Resistance

Panzer, Maruyama,
Wardle, Goodson et al.,
Nanoletters (2010)



Nano Thermal Metrology

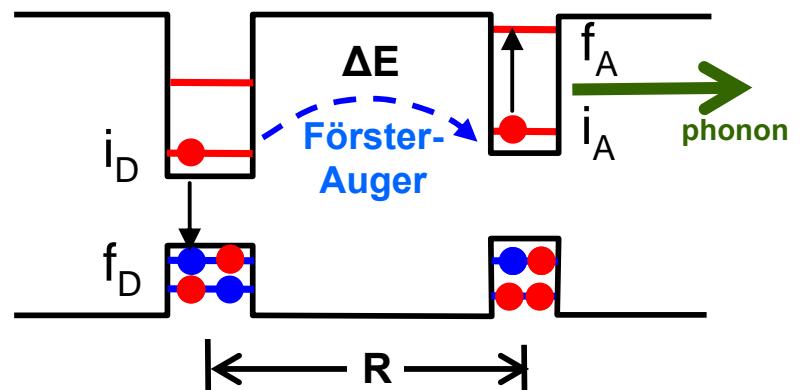
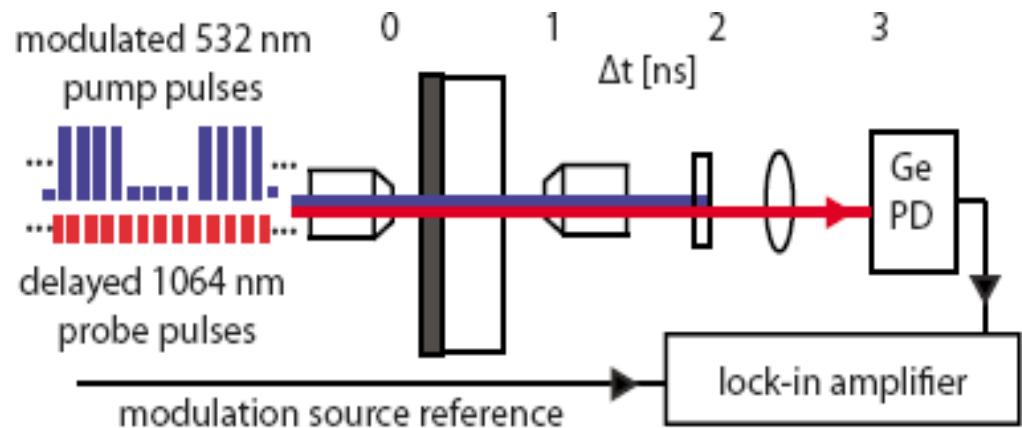
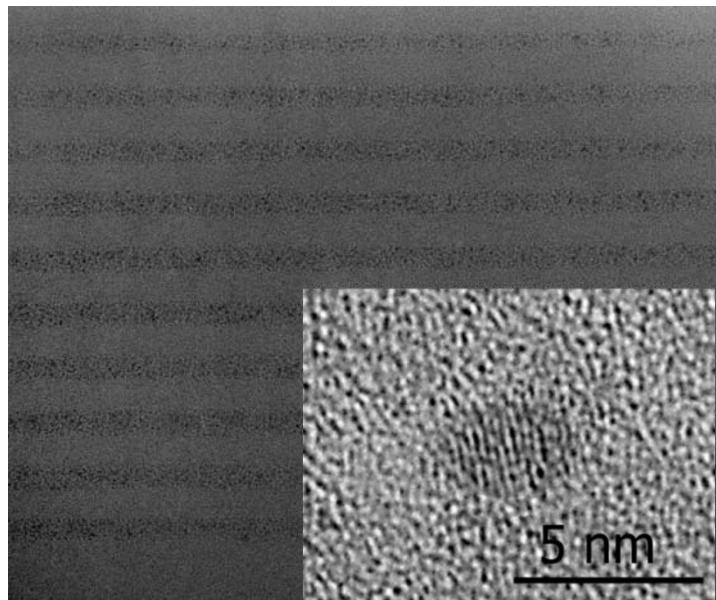
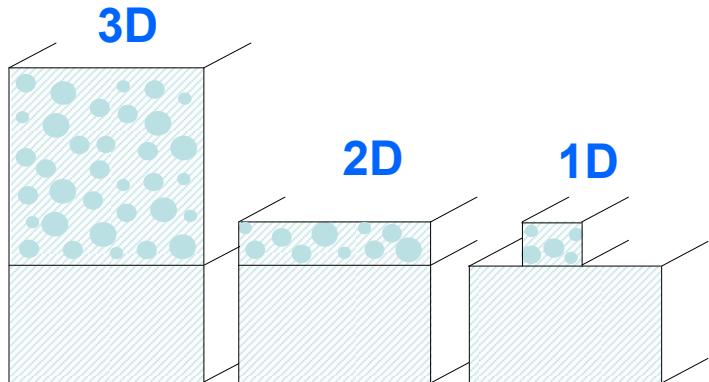
Rig Complexity



Sample Complexity

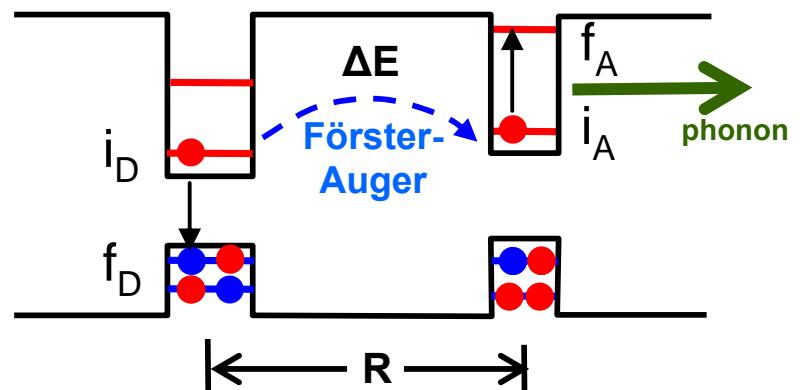
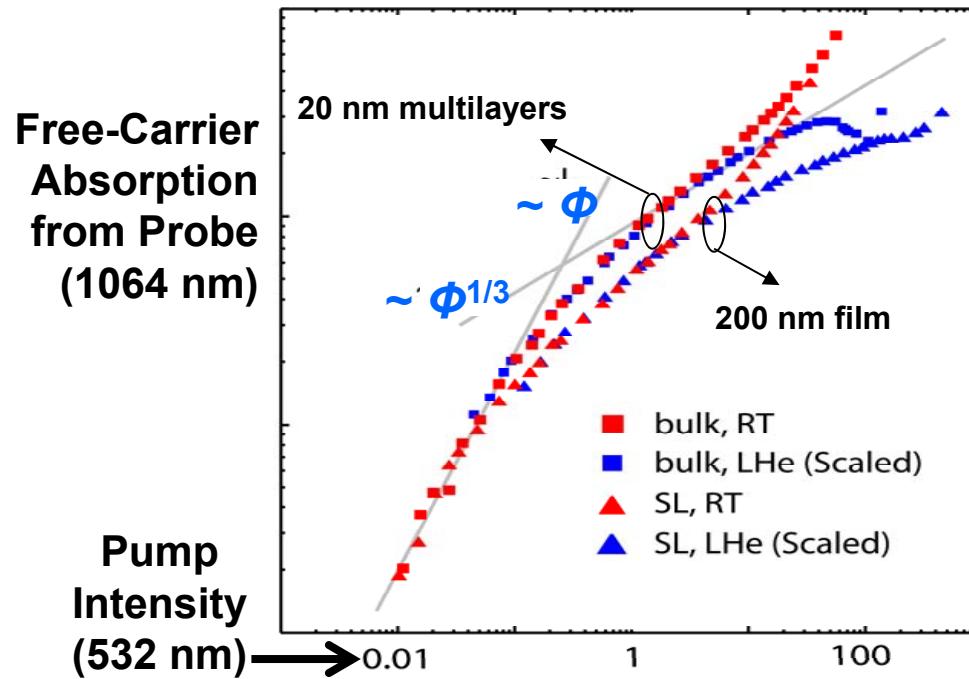
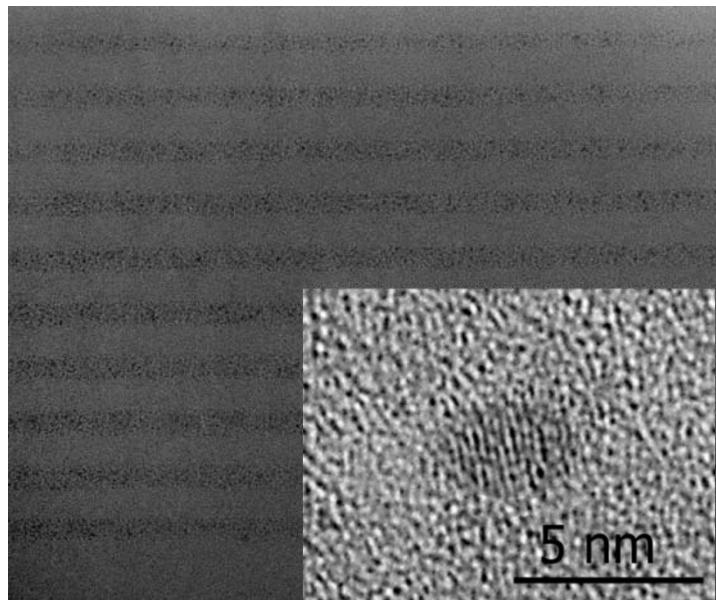
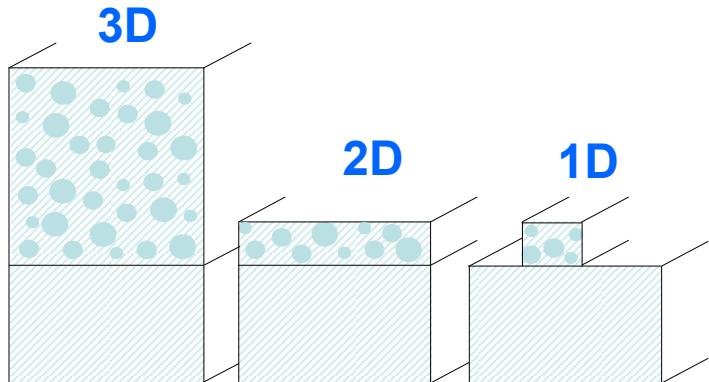
Thermal & Optical Properties of Silicon-Enriched Oxides & Nitrides

Rowlette, Kekatpure, Brongersma, Goodson, et al., *Physical Review B* (2009)
Marconnet, Yerci, Dal Negro, Goodson, et al., *Applied Physics Letters* (2012)

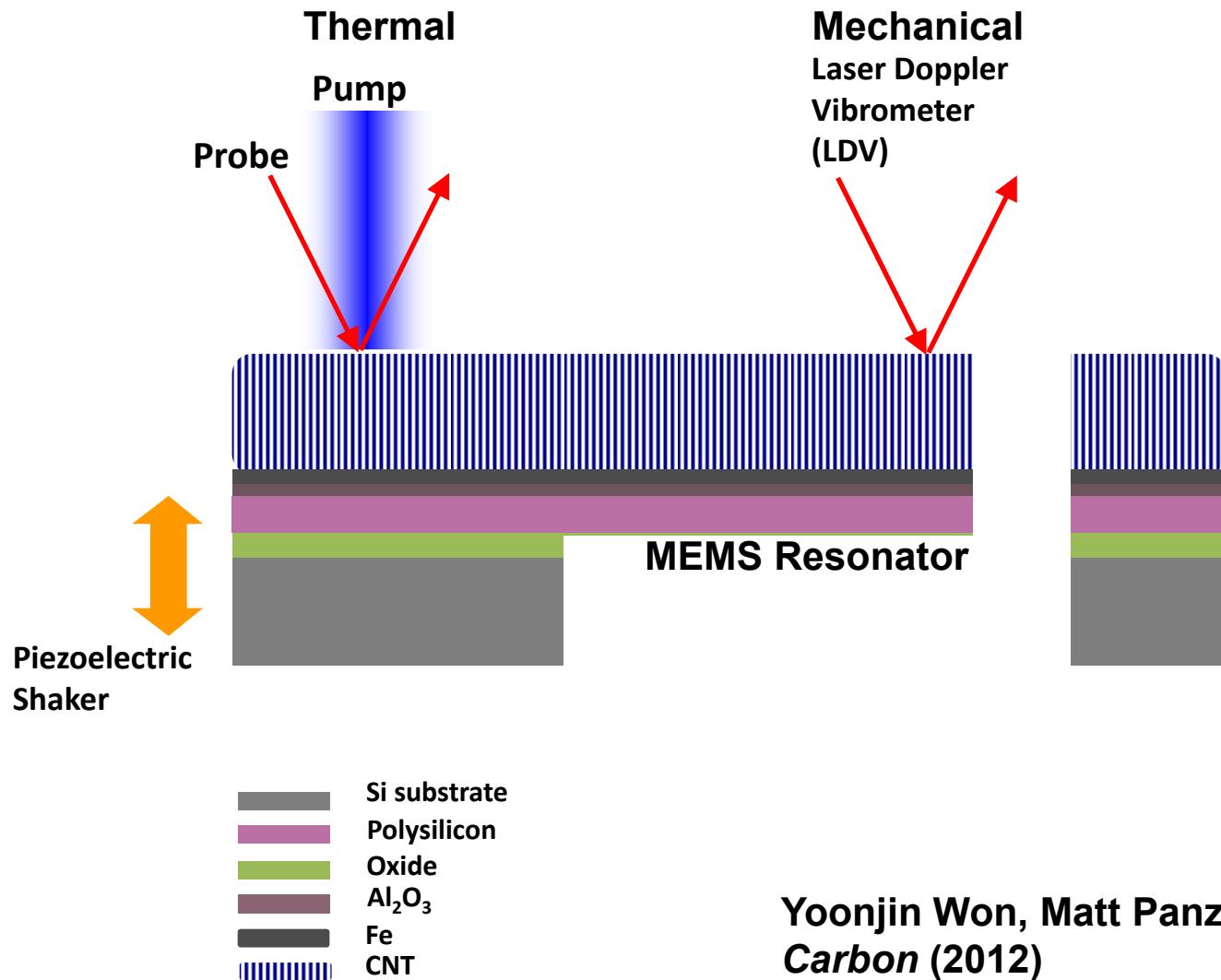


Thermal & Optical Properties of Silicon-Enriched Oxides & Nitrides

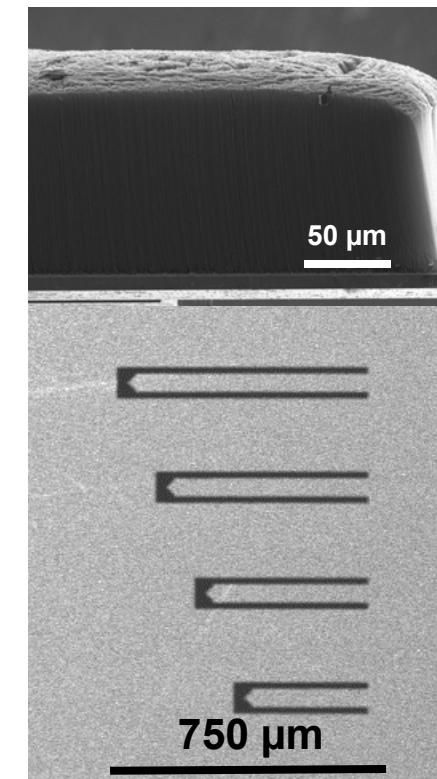
Rowlette, Kekatpure, Brongersma, Goodson, et al., *Physical Review B* (2009)
Marconnet, Yerci, Dal Negro, Goodson, et al., *Applied Physics Letters* (2012)



Mechanical & Thermal Properties of Aligned CNT Films



Yoonjin Won, Matt Panzer, Amy Marconnet, et al.
Carbon (2012)



Fabrication Process

Yoonjin Won, Matt Panzer, Amy Marconnet, et al., CARBON (2012)

Polysilicon deposition



Resonator outline etching



Resonator etching



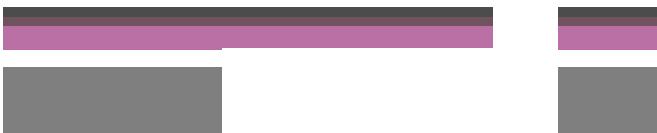
Oxide layer removal



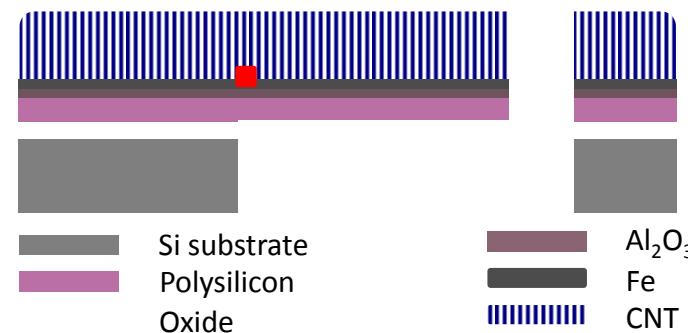
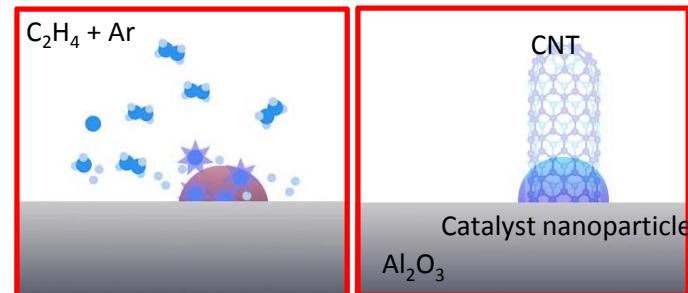
200 Å Al₂O₃ deposition



10 Å Fe catalyst deposition



CNT growth



Si substrate
Al₂O₃
Polysilicon
Oxide

Al₂O₃
Fe
CNT

CNT growth process

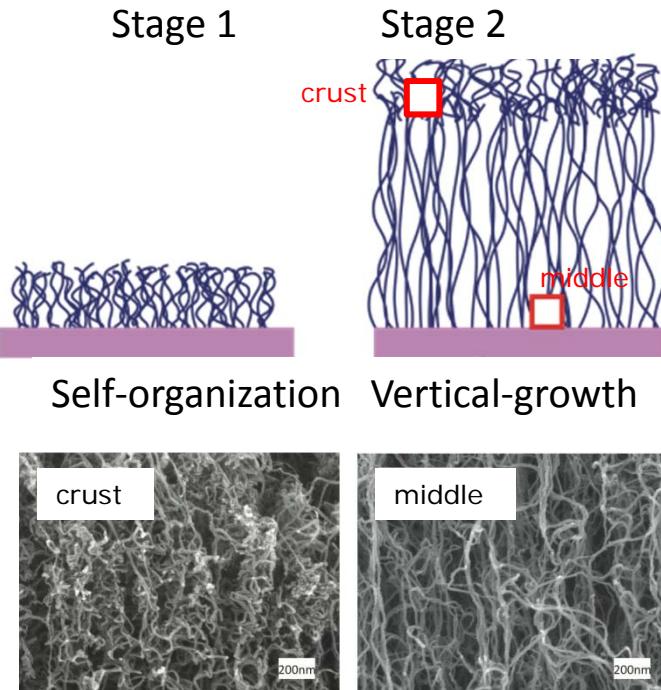
- A mixture of C_2H_4 and Ar gas flows through a tube furnace at 825°C
- The carbon atoms from C_2H_4 dissolve into the catalyst nanoparticles
- The carbons crystallize into stacks of flat sheets of hexagonally patterned carbon, which extrude as nanotubes

Modulus of Nonhomogeneous CNT Films

Yoonjin Won, Matt Panzer, Amy Marconnet, Goodson, et al. CARBON (2012a)

Yuan Gao, Takashi Kodama, Goodson, et al., CARBON (2012b)

Growth Stages



- Interweaving of a thin layer of entangled and randomly oriented nanotubes
- Vertical-aligned growth
- Density decay

Won, Carbon (2011)

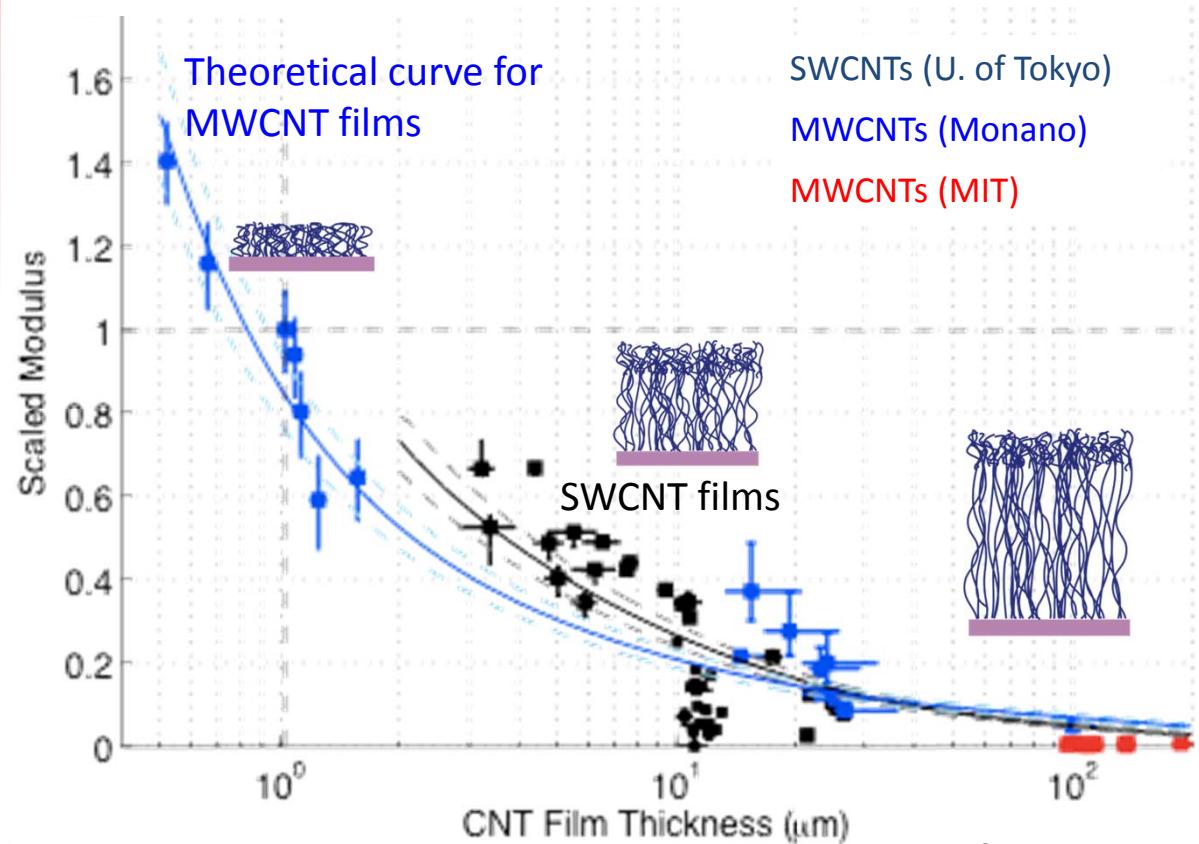
Three-layer Analysis

Two-layer analysis → Three-layer analysis

$$\frac{\Delta w_n}{w_{n,Si,0}} = \sqrt{\frac{E_{Si}I_{Si,1} + E_{Middle}I_{Middle} + E_{Top}I_{Top}}{\rho_{Si}A_{Si} + \rho_{Middle}A_{Middle} + \rho_{Top}A_{Top}}} \cdot \sqrt{\frac{\rho_{Si}A_{Si}}{E_{Si}I_{Si,0}}} - 1$$

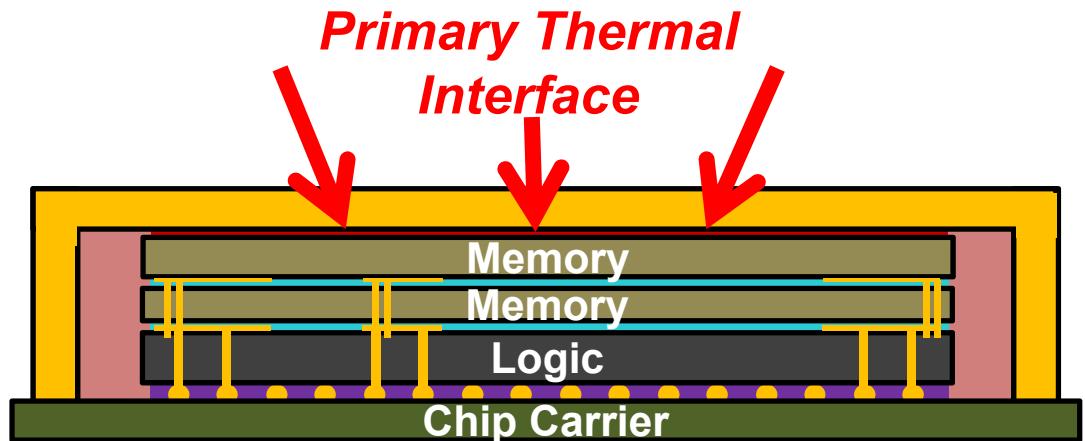
Dimensionless Effective Modulus

: Moduli are scaled by reference sample and volume fraction



3D NanoPackaging

The screenshot shows the EE Times News & Analysis website. The main navigation bar includes Home, News & Analysis, Business, EE Life, Embedded.com, and Design. Under News & Analysis, there are links for Latest News and Semiconductor News. A sidebar for 'DESIGN STRATEGIES FOR ARM® SYSTEMS' features a 'REGISTER NOW' button. The main content area displays a news article titled 'Nanotape could make solder pads obsolete' by R. Colin Johnson, dated 1/24/2011 12:01 AM EST. The article discusses how nanotape material could replace solder pads. It includes a quote from PORTLAND, Ore.: "Solder pads could soon be made obsolete by nanotape material created by the Semiconductor Research Corp. and Stanford University. By sandwiching thermally conductive carbon nanotubes between



Carbon

Mechanical characterization of aligned multi-walled carbon nanotube films using microfabricated resonators

2012

Yoonjin Won ^{a,*}, Yuan Gao ^a, Matthew A. Panzer ^a, Senyo Dogbe ^b, Lawrence Pan ^c, Thomas W. Kenny ^a, Kenneth E. Goodson ^a

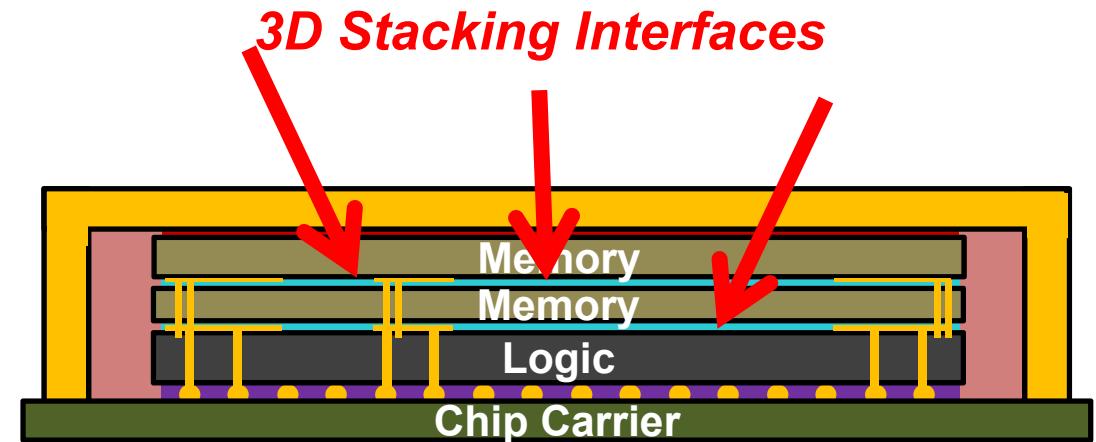
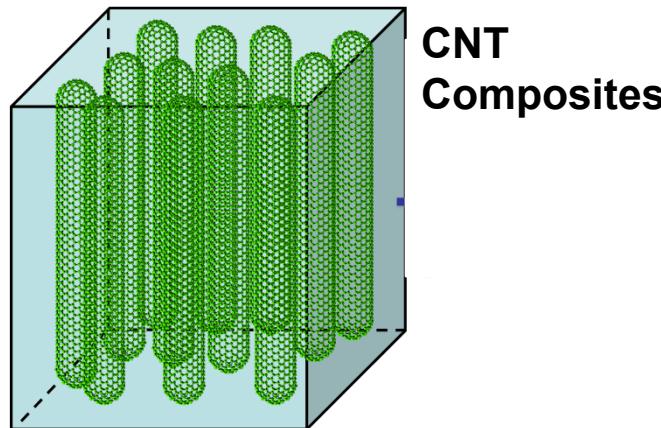
**NANO
LETTERS**

Temperature-Dependent Phonon Conduction and Nanotube Engagement in Metalized Single Wall Carbon Nanotube Films

2010

Matthew A. Panzer,[†] Hai M. Duong,^{||} Jun Okawa,[§] Junichiro Shiomi,[§] Brian L. Wardle,[†] Shigeo Maruyama,[§] and Kenneth E. Goodson^{†,*}

3D NanoPackaging



ACS NANO

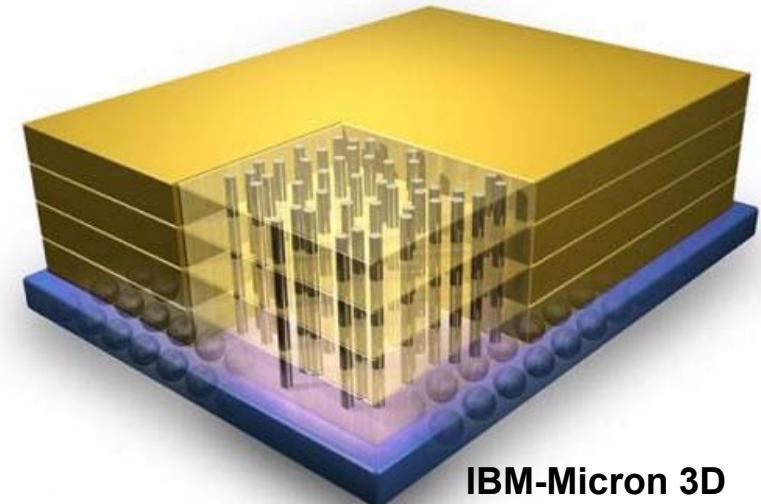
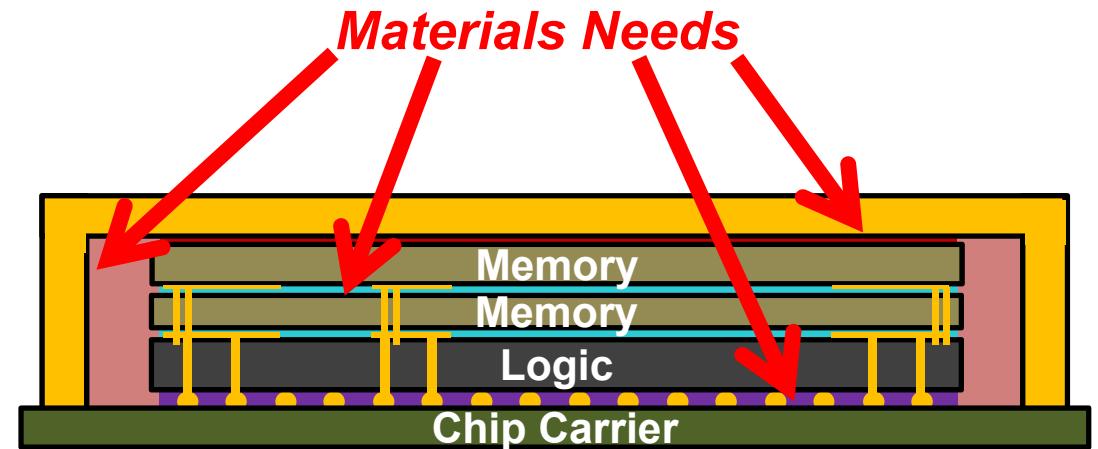
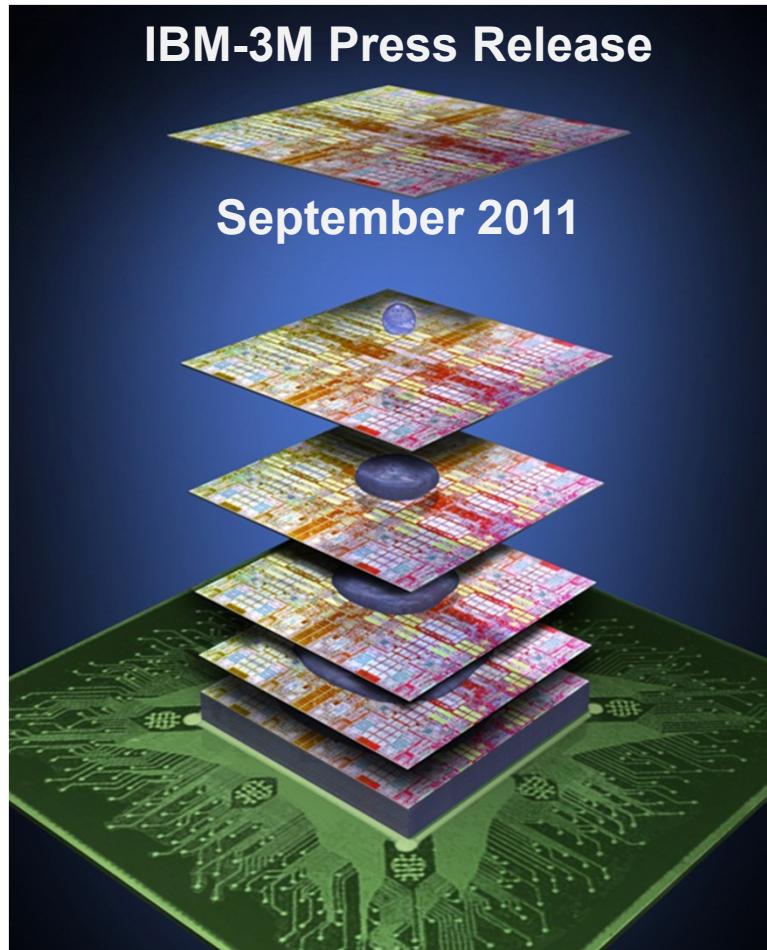
Thermal Conduction in Aligned
Carbon Nanotube–Polymer
Nanocomposites with High Packing
Density

2011

ARTICLE

Amy M. Marconnet,[†] Namiko Yamamoto,[‡] Matthew A. Panzer,[†] Brian L. Wardle,[‡] and Kenneth E. Goodson^{†,*}

3D NanoPackaging



IBM-Micron 3D
press release,
December 2011

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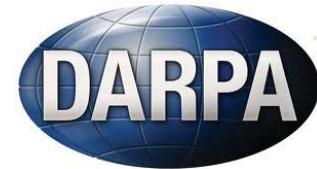
defense

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Josef Miler
Michael Barako
Jaeho Lee
Sri Lingamneni
Saniya Leblanc
Jungwan Cho

Elah Bozorg-Grayeli
Amy Marconnet
Shilpi Roy (EE)
Yuan Gao
Yiyang Li (MSE)
Zijian Li

Ken Goodson

Lewis Hom
Aditja Sood (MSE)
Woosung Parc

Dr. Takashi Kodama
Dr. Yoonjin Won
Prof. Mehdi Asheghi

Selected Alumni

Prof. Dan Fletcher	UC Berkeley	Dr. Jeremy Rowlette	Daylight Solns
Prof. Evelyn Wang	MIT	Dr. Patricia Gharagozloo	Sandia Labs
Prof. Katsuo Kurabayashi	U. Michigan	Dr. Per Sverdrup	Intel
Prof. Sungtaek Ju	UCLA	Dr. Chen Fang	Exxon-Mobile
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